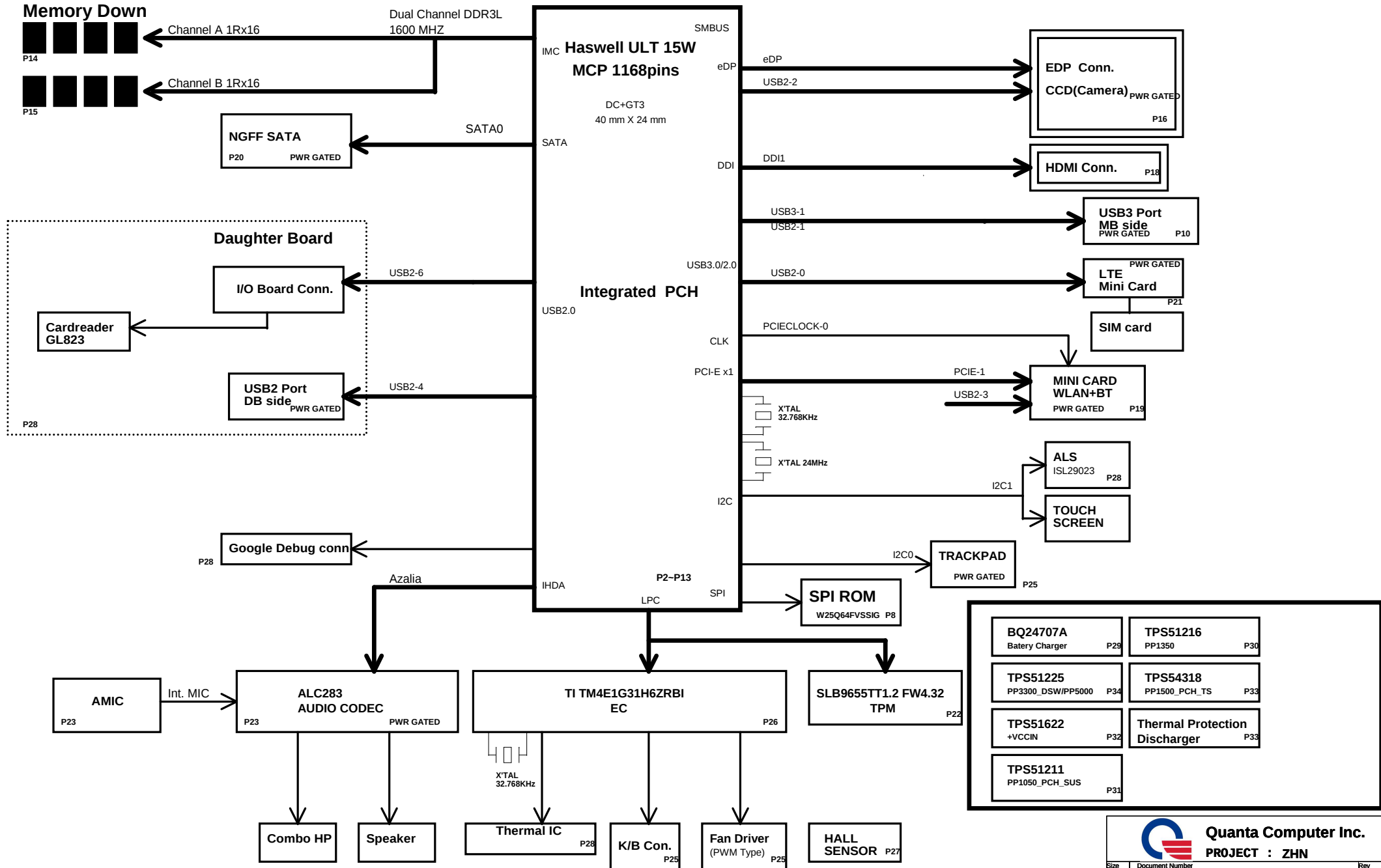
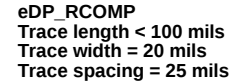


ZHN SHB ULT SYSTEM BLOCK DIAGRAM

01



02



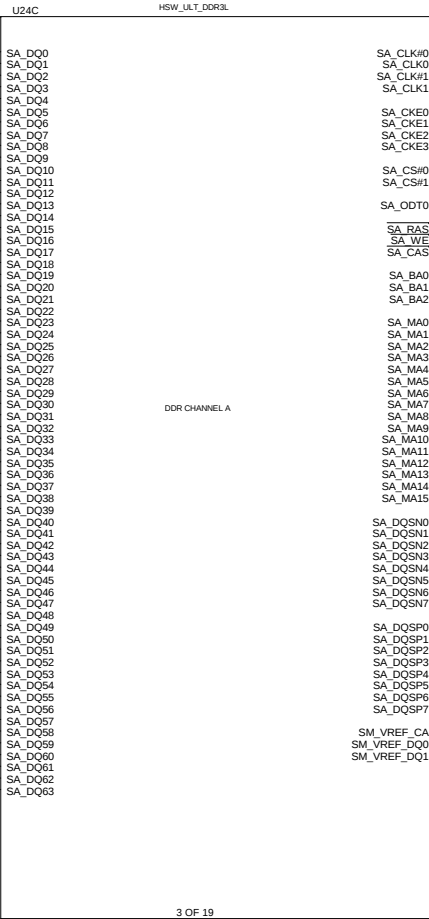
PROJECT : ZHN

Haswell 1/5 (DDI/eDP)

Rev
3B

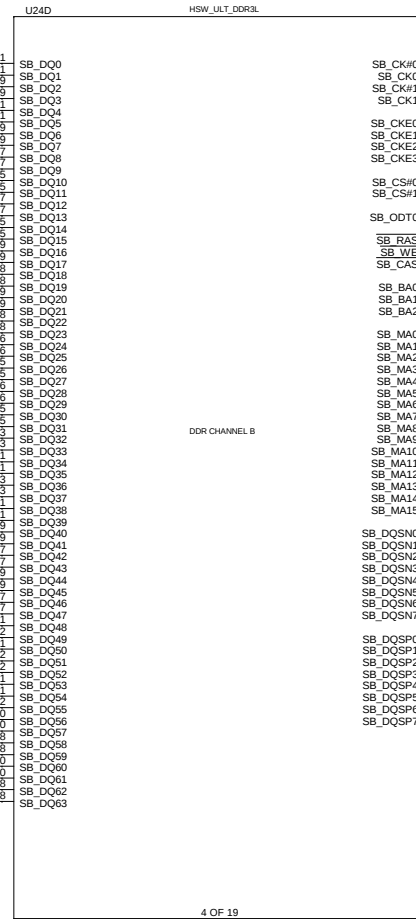
Sheet 2 of 39

Haswell ULT (DDR3L)



3 OF 19

Haswell Processor (DDR3L)



4 OF 19

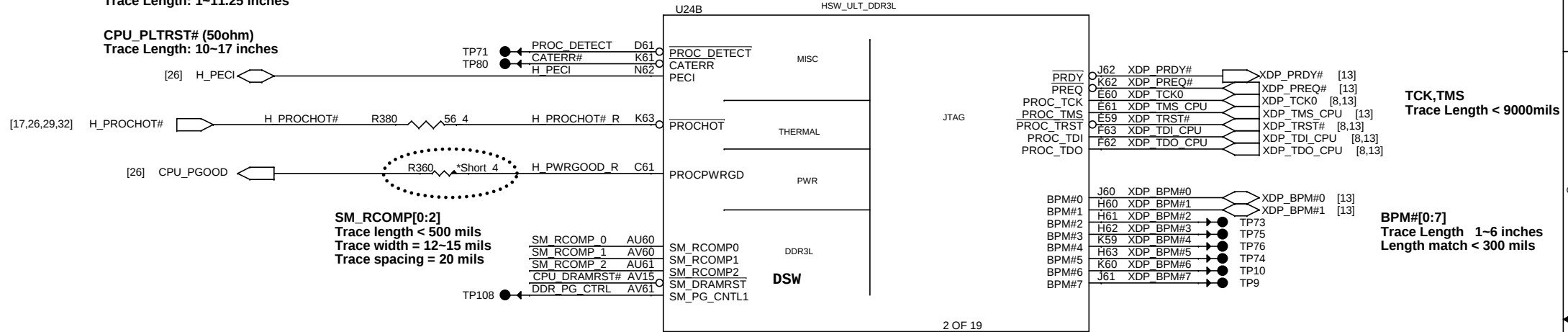
03

Haswell ULT (SIDE BAND)

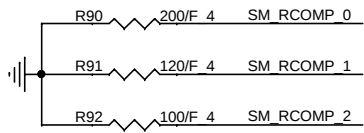
H_PECI (50ohm)
Route on microstrip only
Spacing >18 mils
Trace Length: 0.4~6.125 inches

H_PWRGOOD (50ohm)
Trace Length: 1~11.25 inches

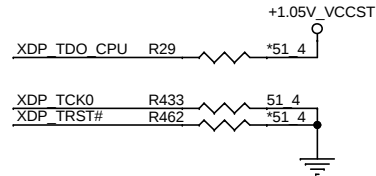
CPU_PLTRST# (50ohm)
Trace Length: 10~17 inches



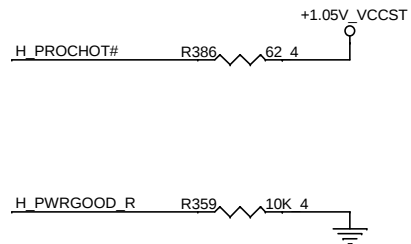
DRAM COMP



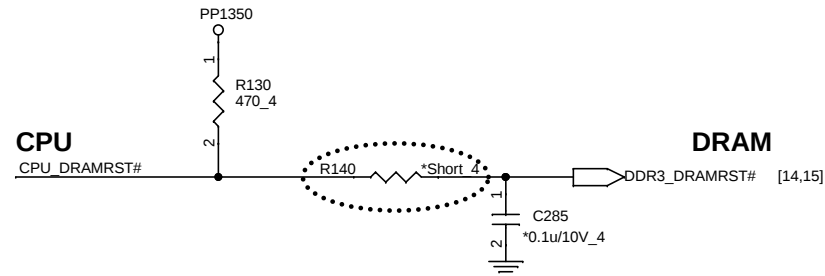
XDP PU/PD



PU/PD of CPU



DRAMRST

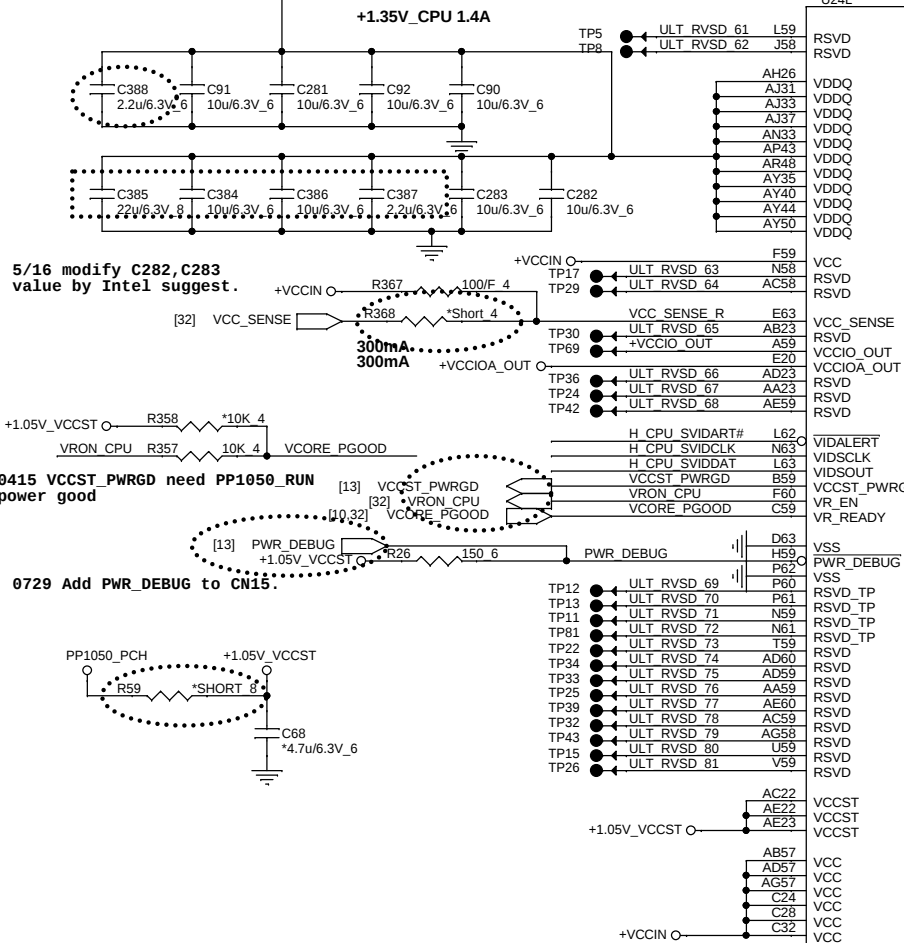


Haswell ULT (POWER)

VDDQ Output Decoupling Recommendations

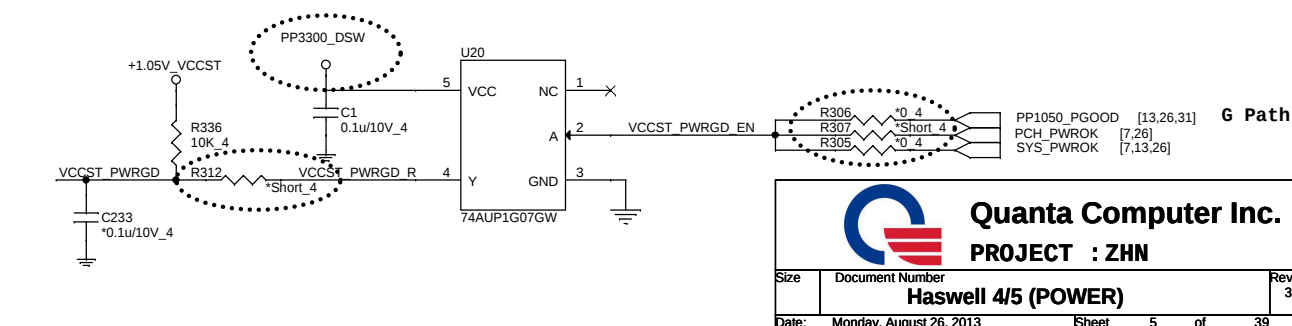
330uFx2	7343	BOT socket side
22uFx11	0805	5 on TOP, 6 on BOT inside socket cavity
10uFx10	0805	5 on TOP, 5 on BOT inside socket cavity

6/21 Add C384-C388 by Intel DDR.

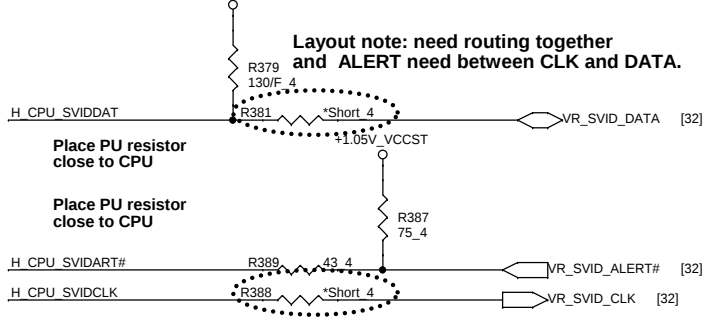


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VCCST PWRGD



SVID

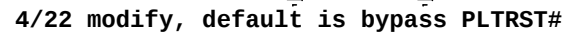




Quanta Computer Inc.
PROJECT : ZHN

Size	Document Number	Rev
	Haswell 5/5 (CFG/GND)	3B
Date:	Monday, August 26, 2013	Sheet 6 of 39

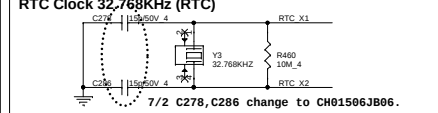
07



PROJECT : ZHN

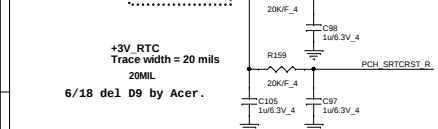
Size	Document Number PCH 1/6 (PM)	Rev 3B
Date:	Monday, August 26, 2013	Sheet 7 of 39

RTC Clock 32.768KHz (RTC)



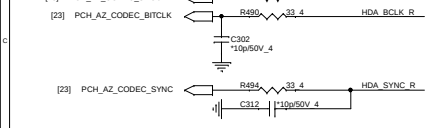
7/2 C278, C286 change to CH01506J806.

RTC Circuitry (RTC)

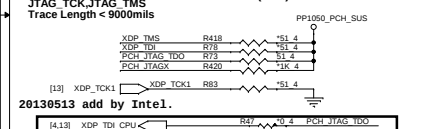


6/18 del D9 by Acer.

HDA



PCH JTAG

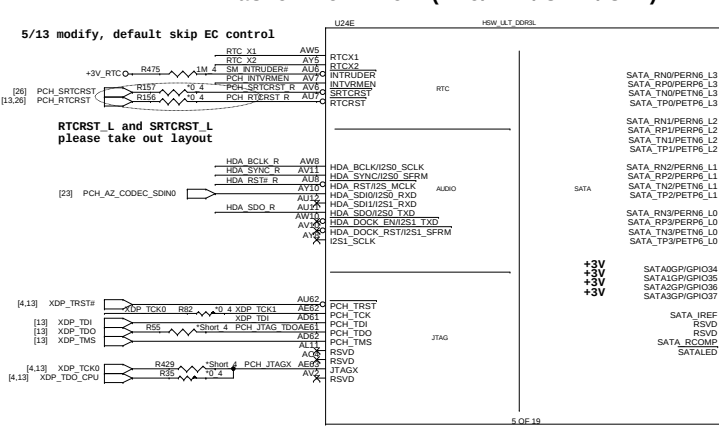


20130513 add by Intel.

ULT Strapping Table

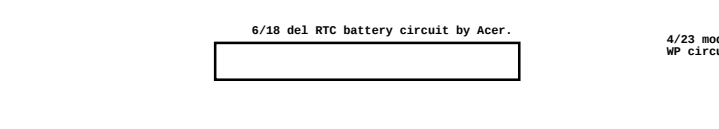
Pin Name	Strap description	Sampled	Configuration
GPIOB1 (SPKR)	No reboot on TCO Timer expiration	PWROK	0 = Default enable (IPD 20K) 1 = Disable No-Reboot mode
HDA_SDO	Flash Descriptor Security Override / Intel ME Debug Mode	PWROK	0 = Default can program ME (IPD 20K) 1 = can't program ME
INTVRMEN	Integrated 1.05V VRM enable	ALWAYS	1 = Should be always pull-up
GPIO66	Top-Block Swap override		0 = Default disable (IPD 20K) 1 = Enable TBS function
GPIO86	Boot BIOS Strap Bit		0 = Default SPI (IPD 20K) 1 = LPC
GPIO15	TLS (Transport layer security)		0 = Default enable w/o confidentiality (IPD 20K) 1 = Default enable with confidentiality
CFG4	DP presence strap		0 = Enable an external display port is connected to the eDP 1 = disable
DSWVREN	Deep Sx well on the VR enable		1 = Should be always pull-up

Haswell ULT PCH (RTC/HDA/SATA/SPI)

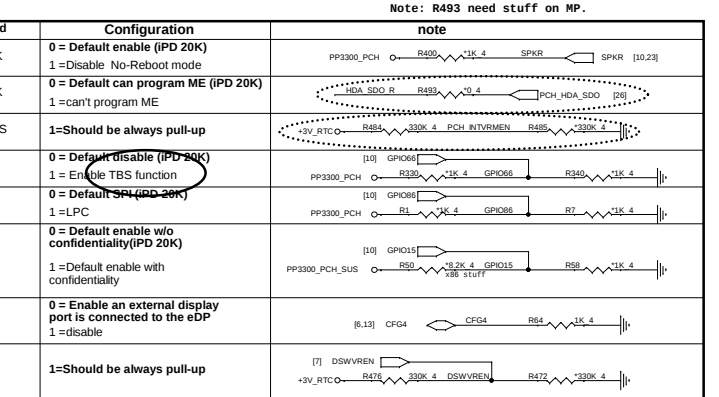


6/18 del RTC battery circuit by Acer.

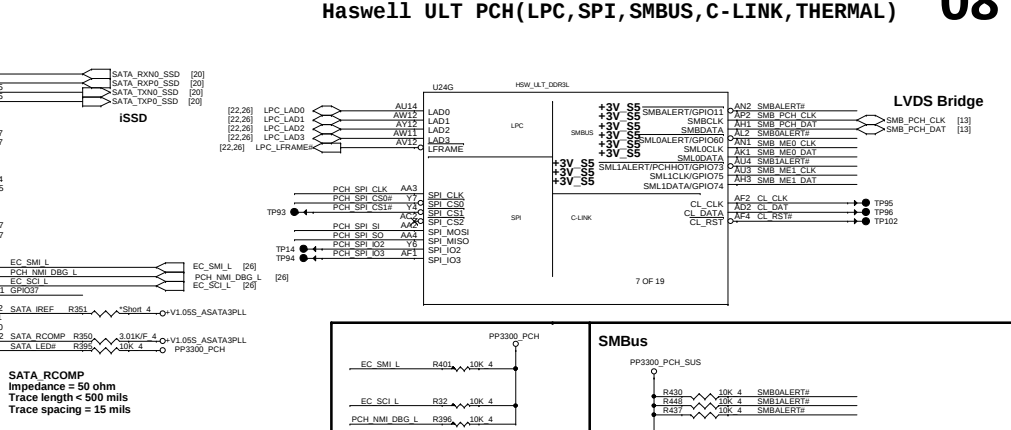
4/23 modify WP circuit



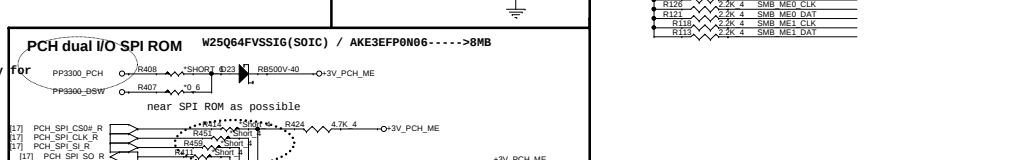
Note: R493 need stuff on MP.



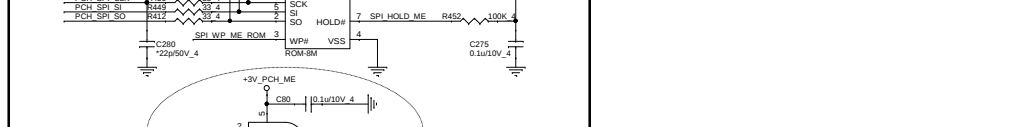
Haswell ULT PCH (LPC, SPI, SMBUS, C-LINK, THERMAL)



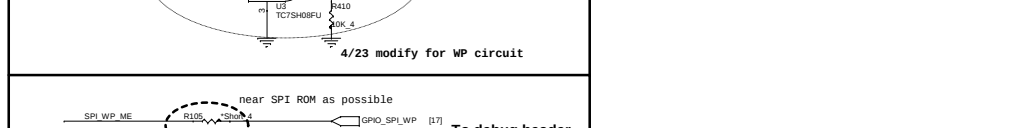
4/23 modify for WP circuit



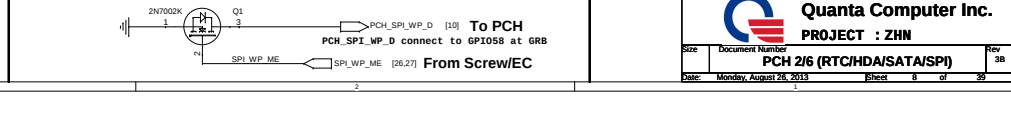
near SPI ROM as possible



near SPI ROM as possible



To debug header

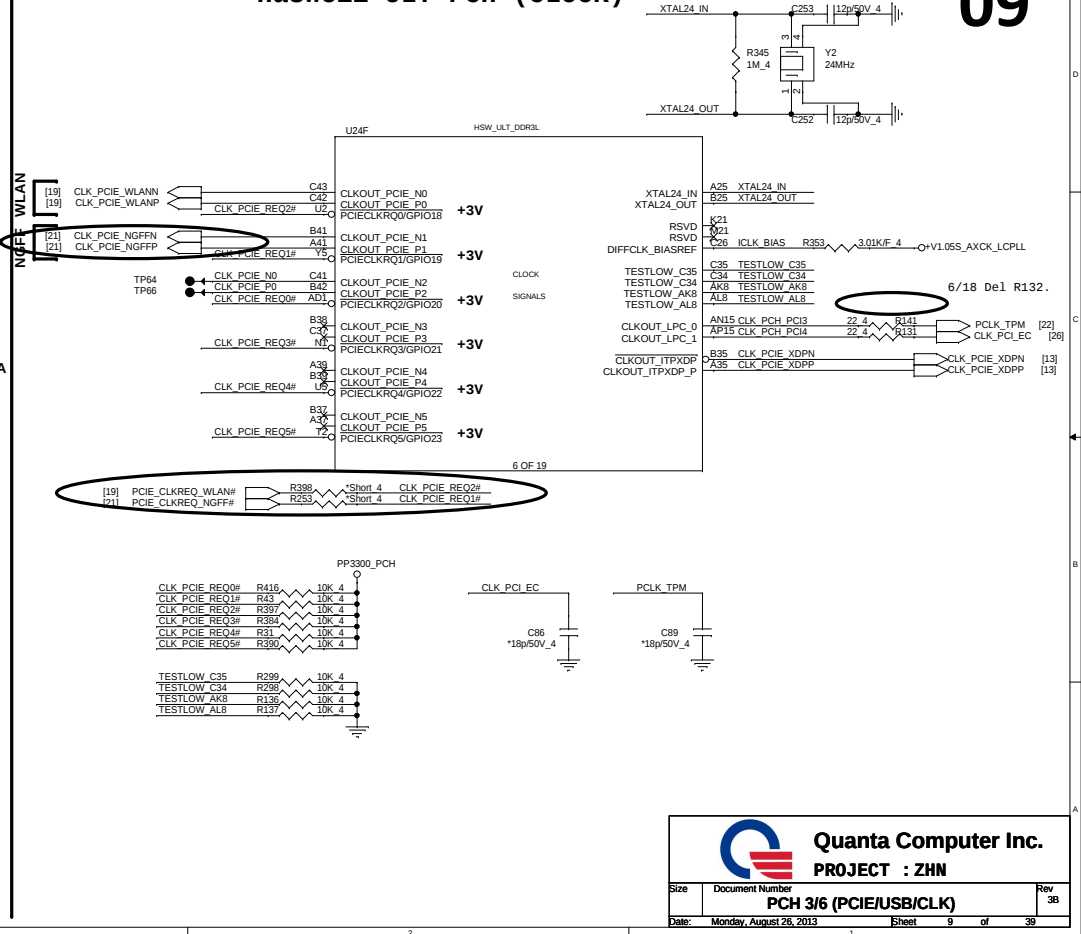




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PROJECT : ZHN

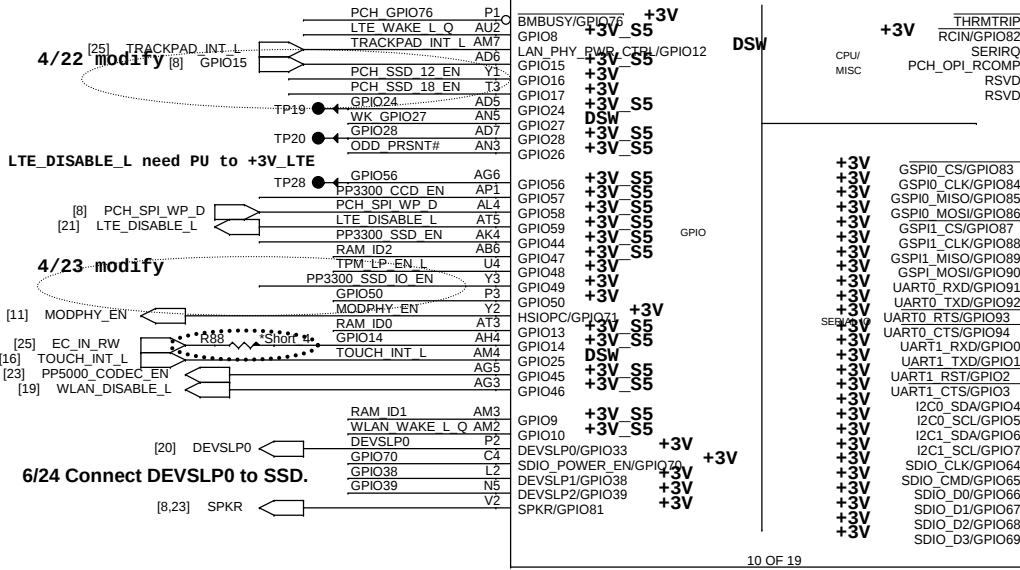
Size	Document Number	Rev
	PCH 2/6 (RTC/HDA/SATA/SPI)	3B
Date	Monday, August 28, 2013	Sheet 8 of 30

09



Haswell ULT PCH (GPIO, CPU/MISC, NCTF)

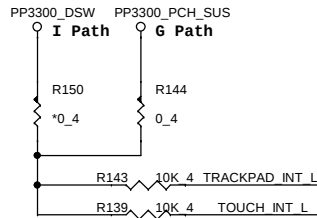
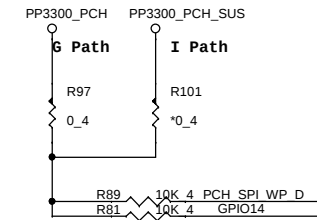
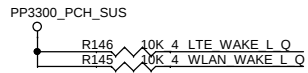
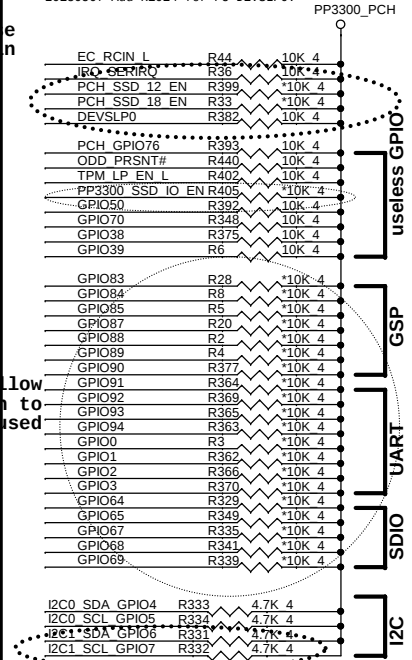
U24J HSW_ULT_DDR3L



PCH GPIO PU/PD

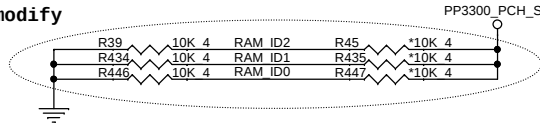
10

20130507 Add R1014 for PU DEVSLP0.

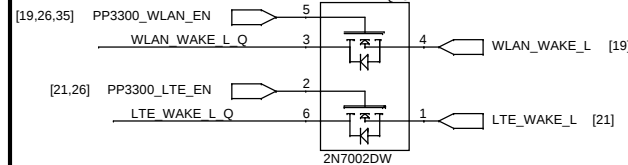


RAM ID

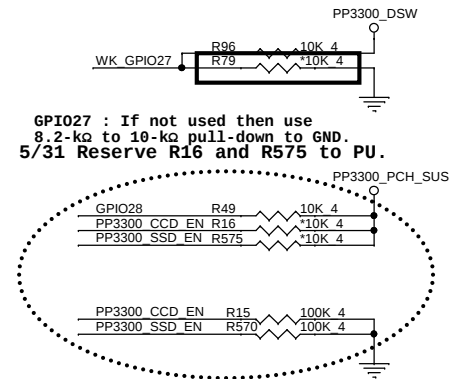
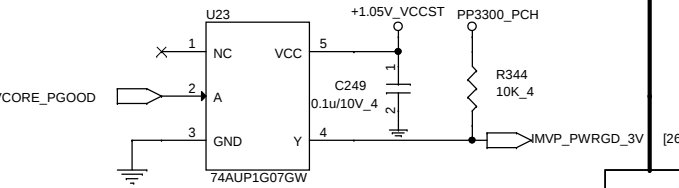
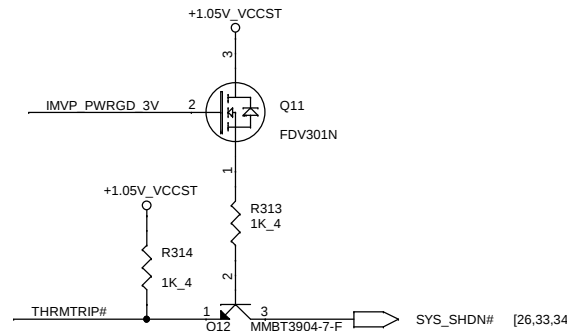
4/22 modify



Vender	RAM_ID			Q PN	Mfr. PN	Freq.
	ID2	ID1	ID0			
Micron(4G)	0	0	0	AKD5JGSTL10	MT41K256M16HA-125:E	1600MHZ
Hynix(4G)	0	0	1	AKD5JGETW04	H5TC4G63AFR-PBA	1600MHZ
Elpida(4G)	0	1	0	AKD5JGST407	EDJ4216EFBG-GNL-F	1600MHZ
Micron(2G)	1	0	0	AKD5JGSTL10	MT41K256M16HA-125:E	1600MHZ
Hynix(2G)	1	0	1	AKD5JGETW04	H5TC4G63AFR-PBA	1600MHZ
Elpida(2G)	1	1	0	AKD5JGST407	EDJ4216EFBG-GNL-F	1600MHZ



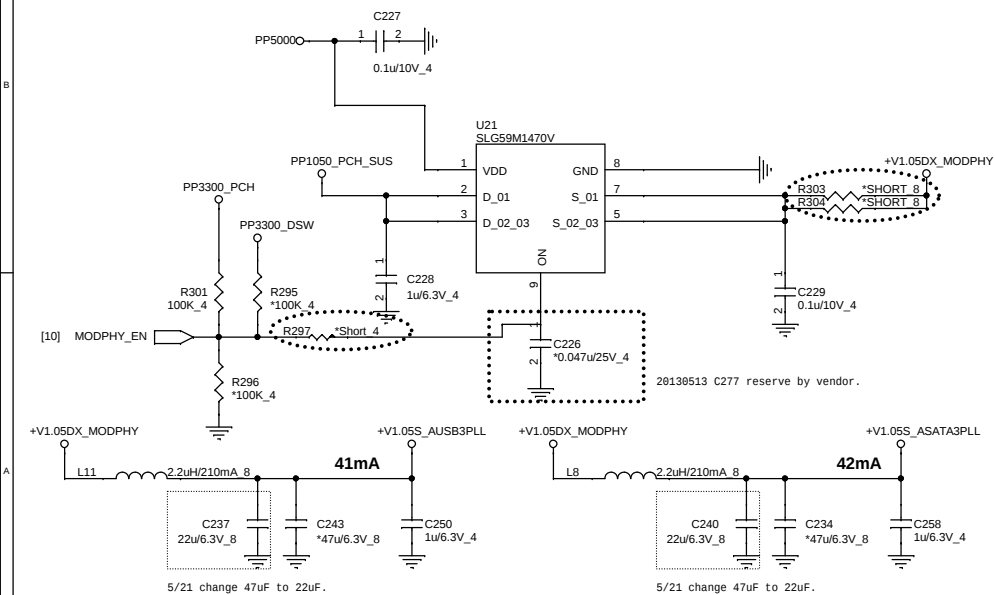
CPU thermal trip



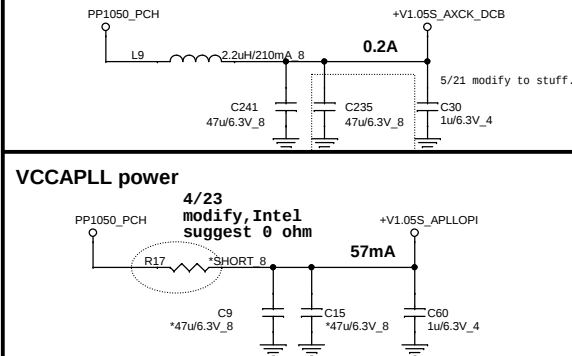
Haswell ULT PCH (Power)

0412 MOW-ww15 a 0.47uF cap between VccDSW3_3 and DcpSusByp is required if the 1.9A inrush current requirement cannot meet

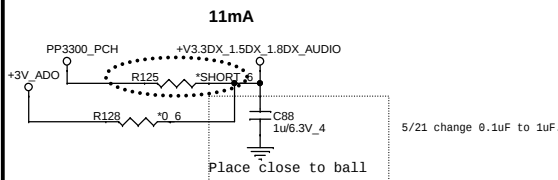
PCH VCCHSIO Power



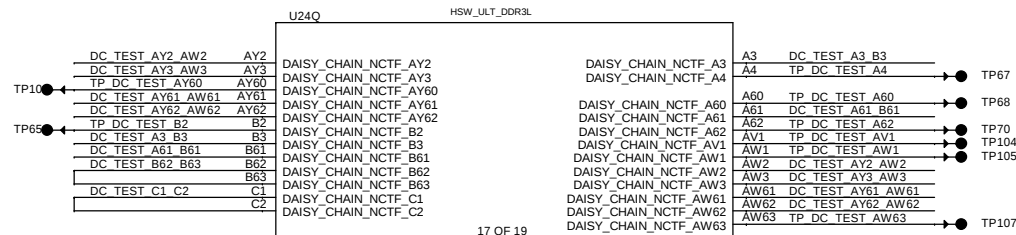
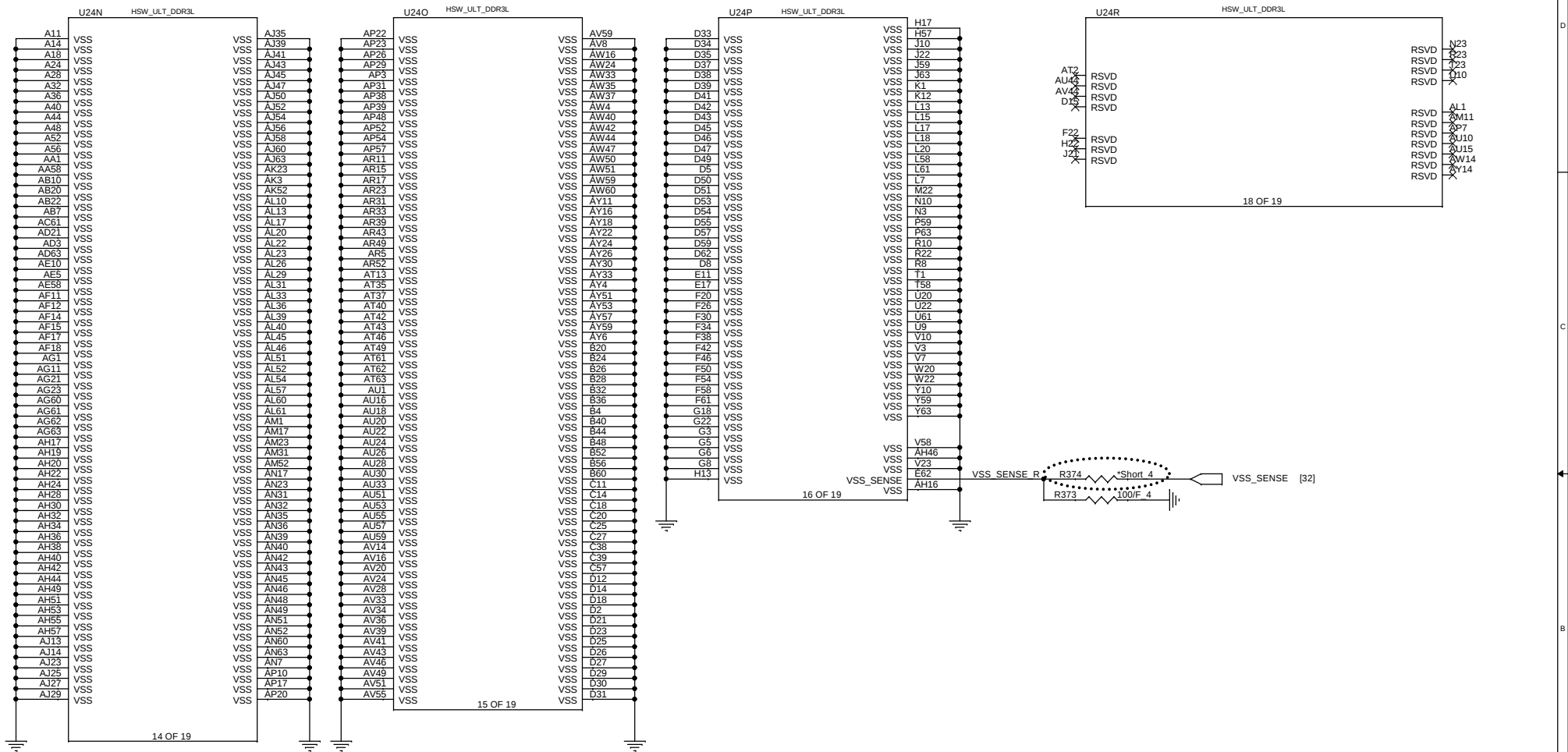
VCCAPLL power

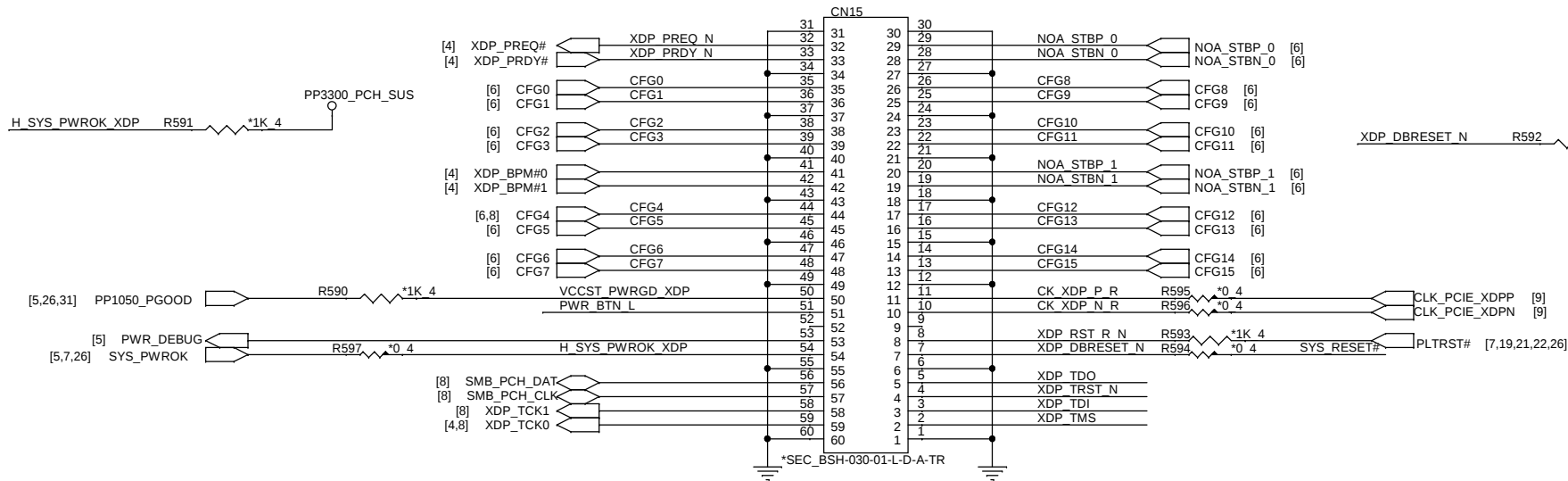


PCH HDA Power	
0	0.000000
1	0.000000
2	0.000000
3	0.000000
4	0.000000
5	0.000000
6	0.000000
7	0.000000
8	0.000000
9	0.000000
10	0.000000
11	0.000000
12	0.000000
13	0.000000
14	0.000000
15	0.000000
16	0.000000
17	0.000000
18	0.000000
19	0.000000
20	0.000000
21	0.000000
22	0.000000
23	0.000000
24	0.000000
25	0.000000
26	0.000000
27	0.000000
28	0.000000
29	0.000000
30	0.000000
31	0.000000
32	0.000000
33	0.000000
34	0.000000
35	0.000000
36	0.000000
37	0.000000
38	0.000000
39	0.000000
40	0.000000
41	0.000000
42	0.000000
43	0.000000
44	0.000000
45	0.000000
46	0.000000
47	0.000000
48	0.000000
49	0.000000
50	0.000000
51	0.000000
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55	0.000000
56	0.000000
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58	0.000000
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62	0.000000
63	0.000000
64	0.000000
65	0.000000
66	0.000000
67	0.000000
68	0.000000
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71	0.000000
72	0.000000
73	0.000000
74	0.000000
75	0.000000
76	0.000000
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79	0.000000
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81	0.000000
82	0.000000
83	0.000000
84	0.000000
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88	0.000000
89	0.000000
90	0.000000
91	0.000000
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95	0.000000
96	0.000000
97	0.000000
98	0.000000
99	0.000000

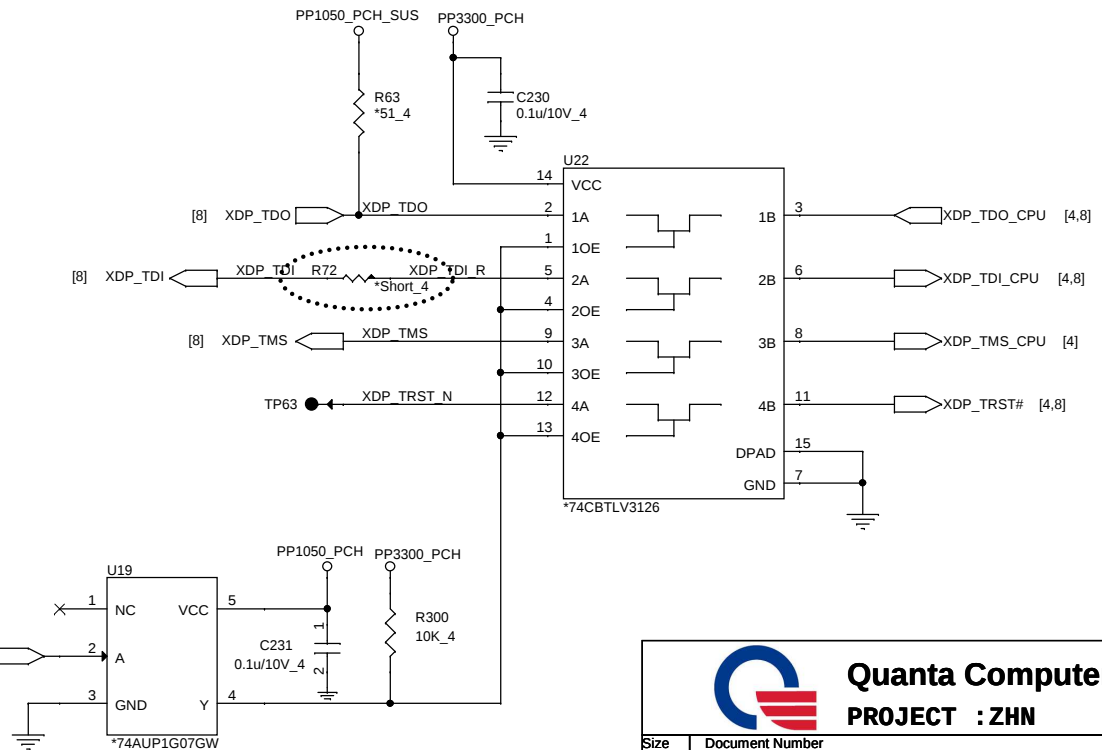
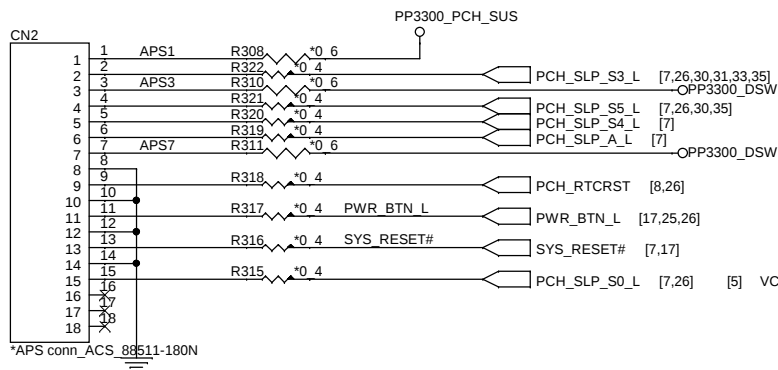


Haswell ULT (GND)





APS



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PROJECT : ZHN

<DDR>

BYTE2_16-23

BYTE3_24-31

BYTE7_56-63

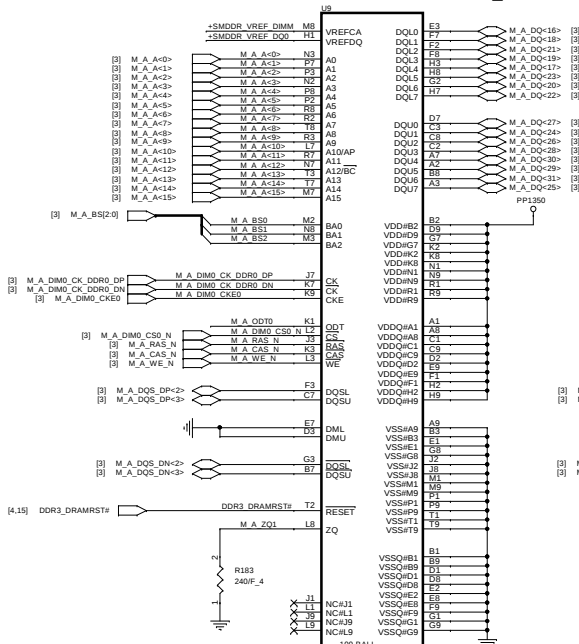
BYTE5_40-47

BYTE0_0-7

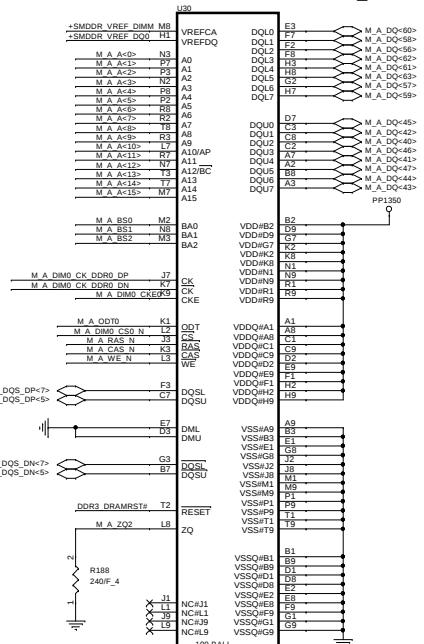
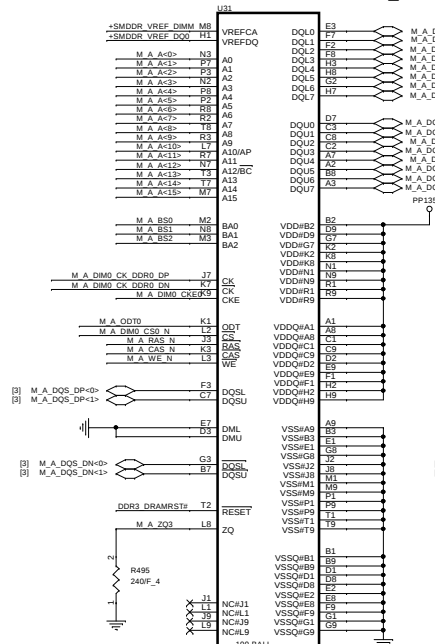
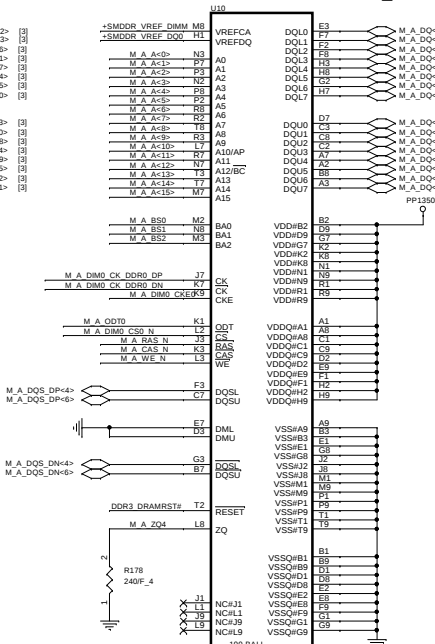
BYTE1_8-15

BYTE4_32-3

BYTE6_48-55

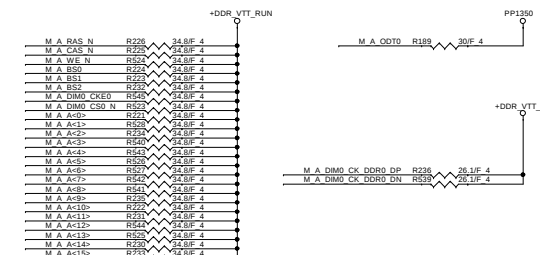


Micron/MT41K256M16HA-125:E/AKD5JGSTL02 for proto board

100-BALL
SDRAM DDR3100-BALL
SDRAM DDR3

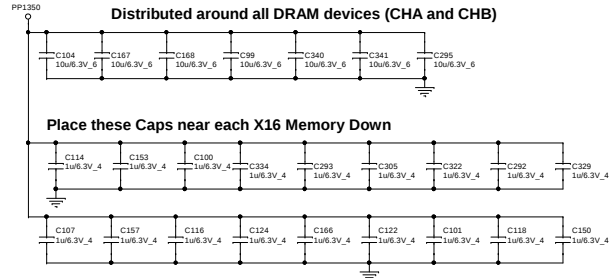
10U-BALL
SDRAM DDR3

Vendor	P/N	
Hynix		
Elpida	AKD5JGST400	DDR3L 1333Mhz 4Gb
	AKD5JGST404	DDR3L 1600Mhz 4Gb

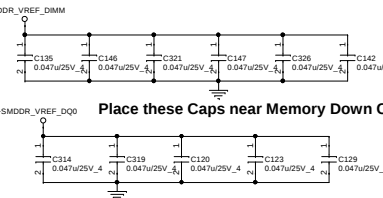


Distributed around all DRAM devices (CHA and CHB)

Place these Caps near each X16 Memory Down



Place these Caps near Memory Down CA & DO pin

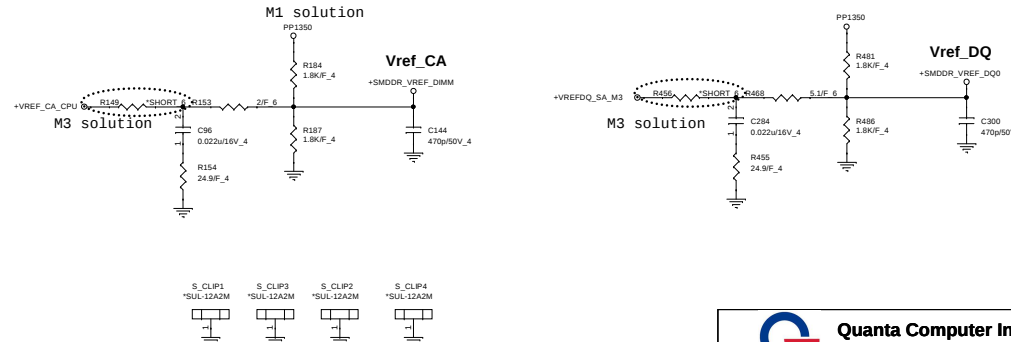


M1 solution

Vref_CA

M1 solution

Vref_D



<DDR>

BYTE1_8-15

BYTE2_16-23

BYTE4_40-47

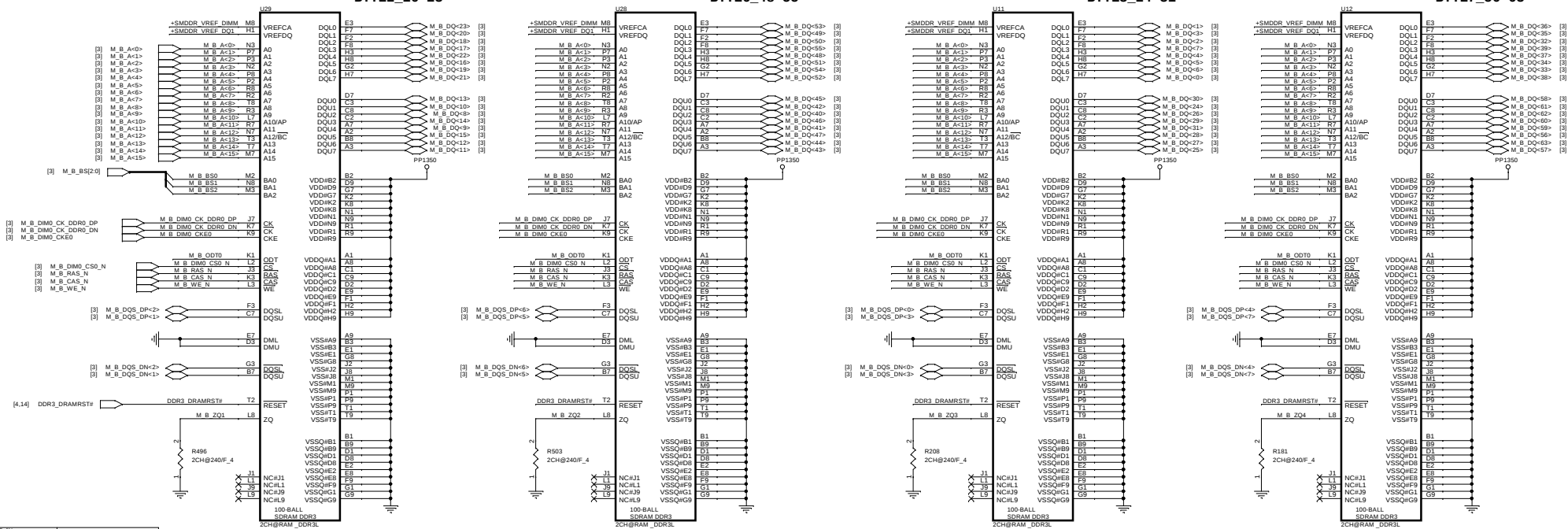
BYTE6_48-55

BYTE0_0-7

BYTE3_24-31

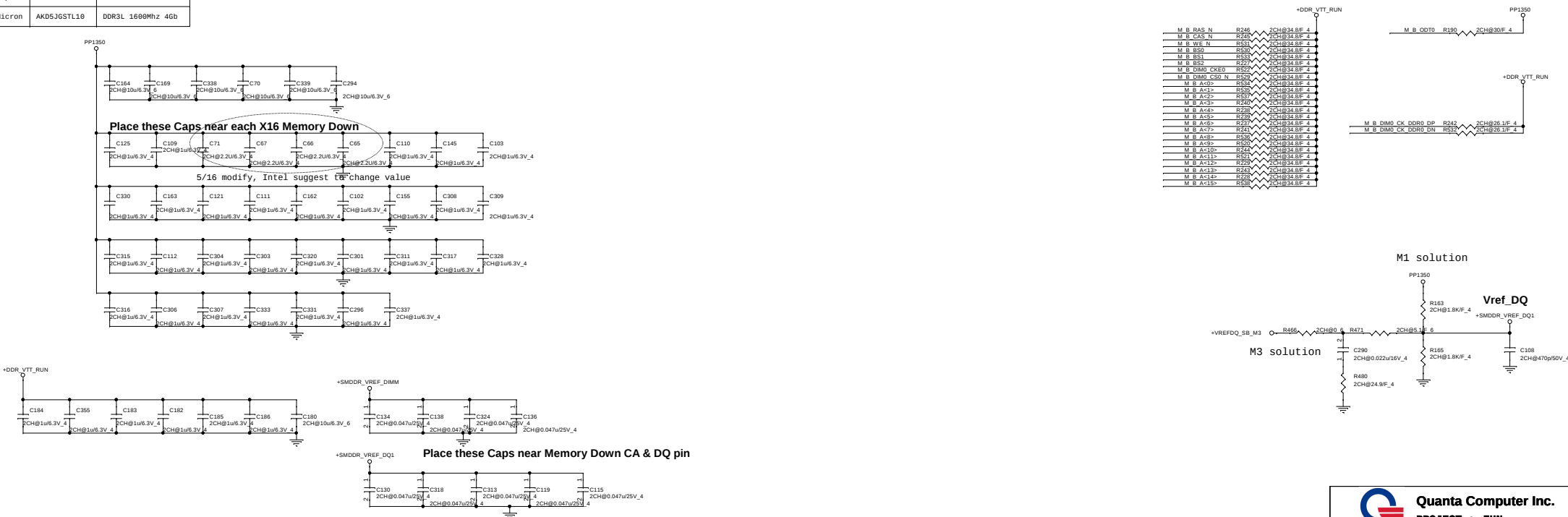
BYTE7_32-39

BYTE7_56-63

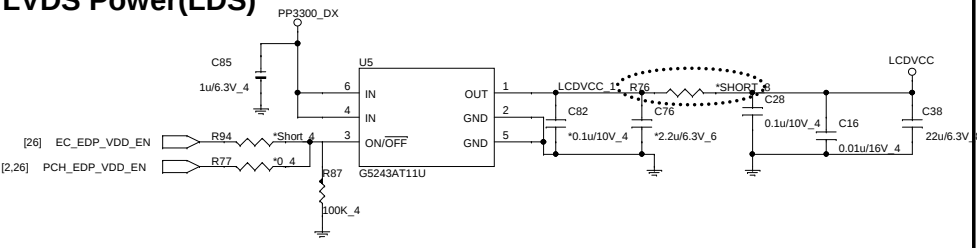


Vendor	P/N
Hynix	AKD5J6ETW04
Elipida	AKD5J6ST407
Micron	AKD5J6STL10

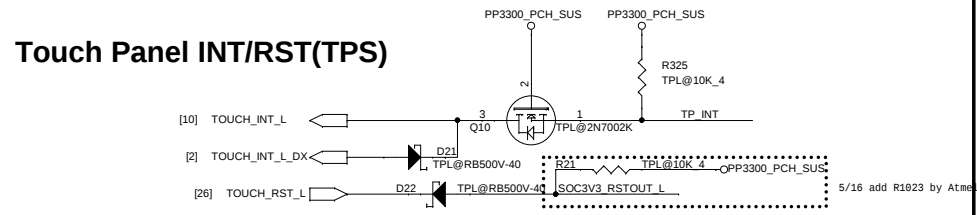
MicronMT41K256M16HA-12S/E/AKD5JGSTL02 for proto board



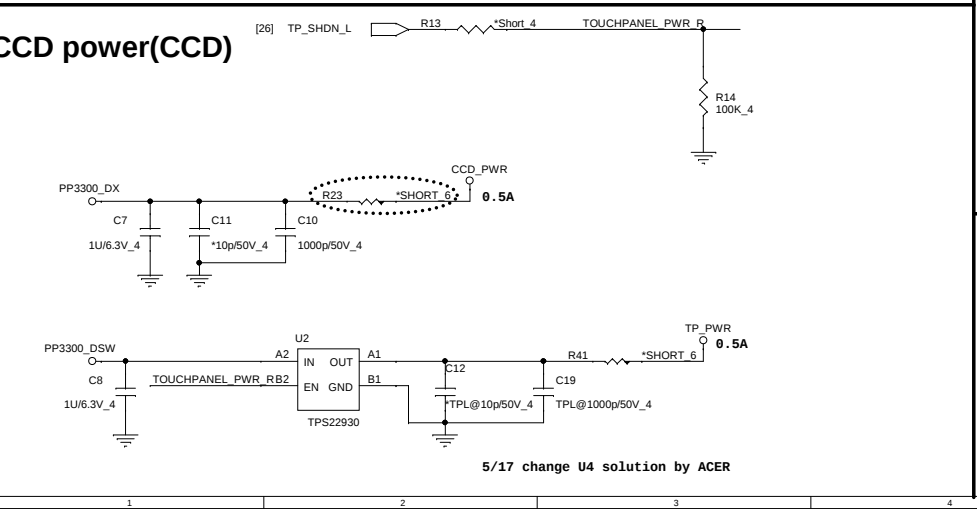
LVDS Power(LDS)



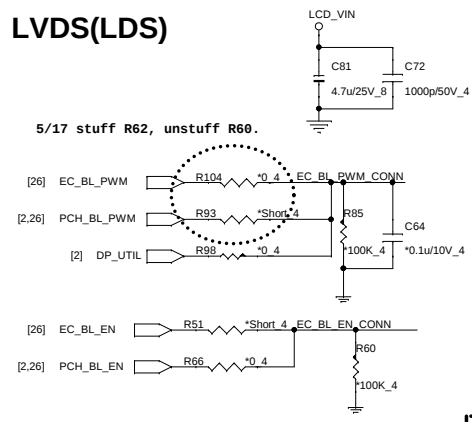
Touch Panel INT/RST(TPS)



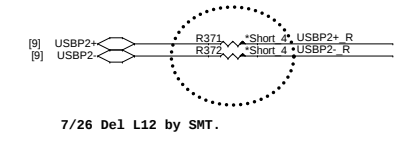
CCD power(CCD)



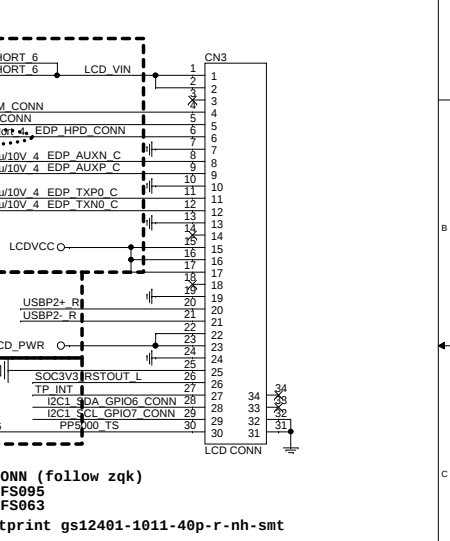
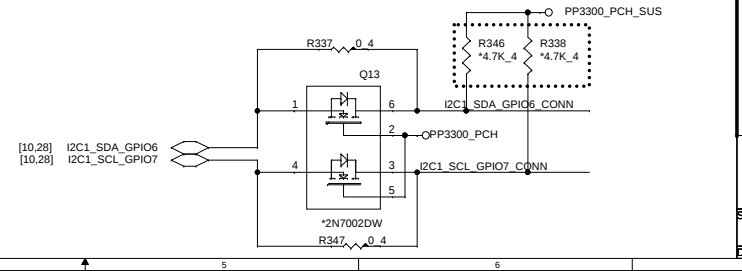
LVDS(LDS)



CCD (CCD)

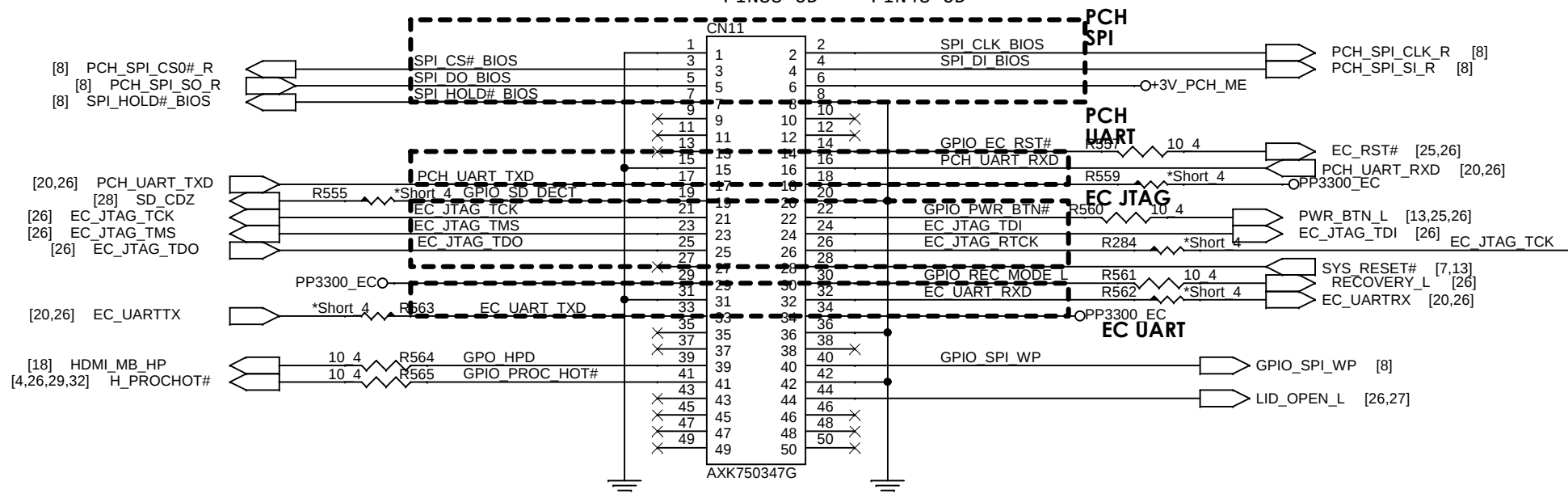


Touch Panel level shift(TPS)



Debug Port(DBG)

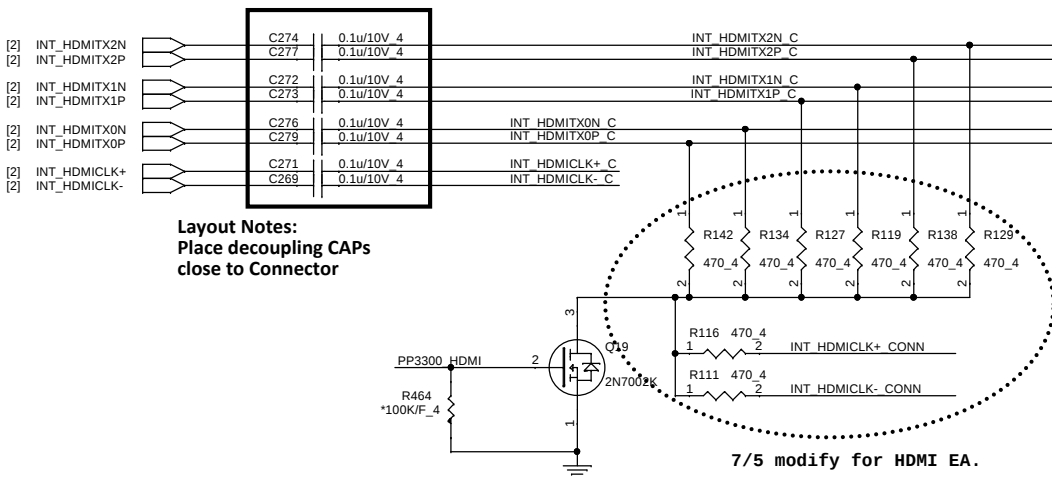
PIN7 OD PIN39 OD PIN49 OD
 PIN14 OD PIN41 OD PIN50 OD
 PIN19 OD PIN43 OD
 PIN22 OD PIN44 OD
 PIN28 OD PIN45 OD
 PIN30 OD PIN46 OD
 PIN37 OD PIN47 OD
 PIN38 OD PIN48 OD



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Size	Document Number	Rev
	Google Debug	3B
Date:	Monday, August 26, 2013	Sheet 17 of 39

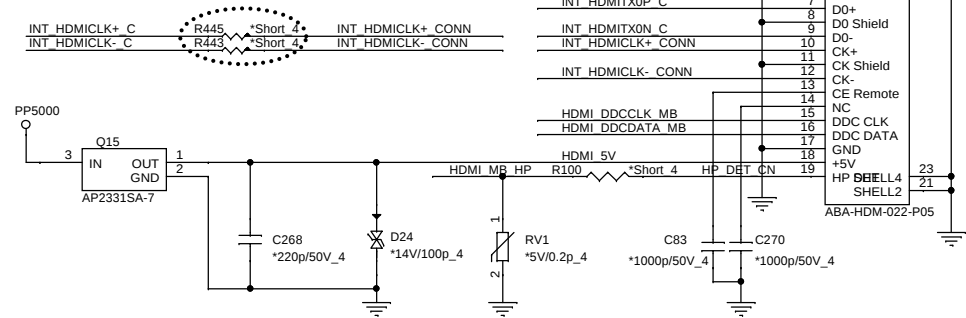
HDMI Cost Reduced level shift (HDM)



HDMI connector (HDM)

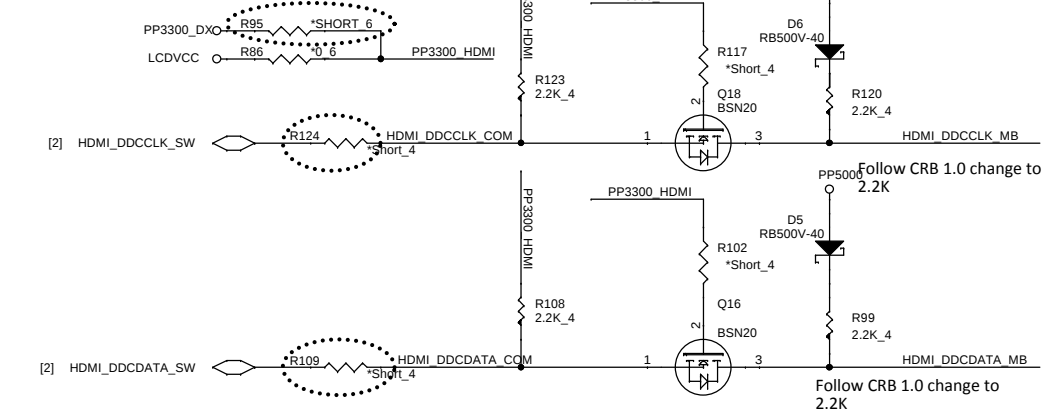
DFHS19FR079
new footprint not ready

8/21 Del L13 and R443, R445
change to shortpad.

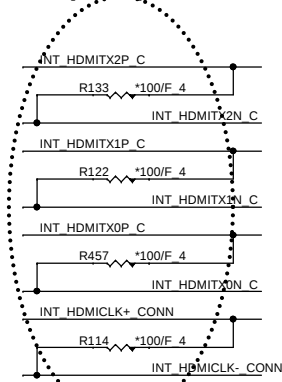


18

HDMI DDC (HDM)

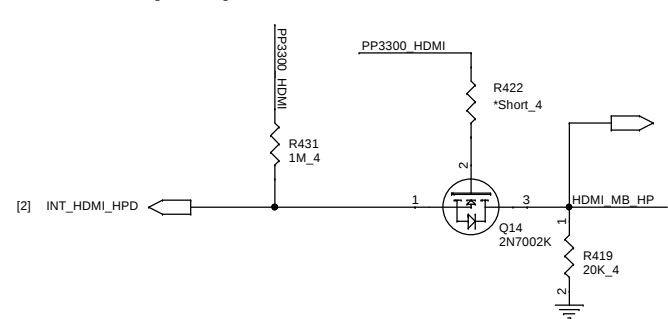


EMI (EMC)



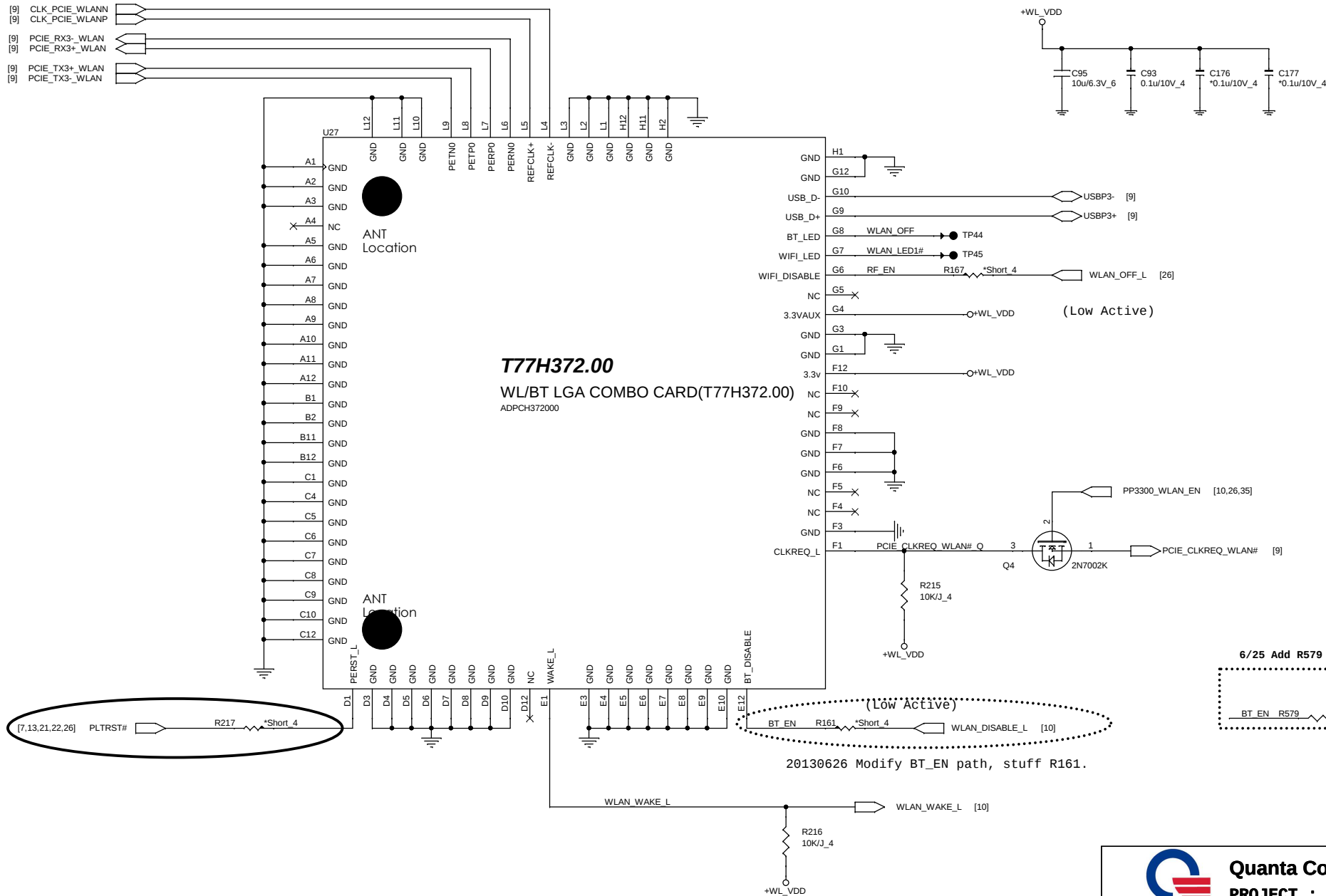
4/22 modify for layout
7/5 unstuff by HDMI EA.

HDMI-detect (HDM)

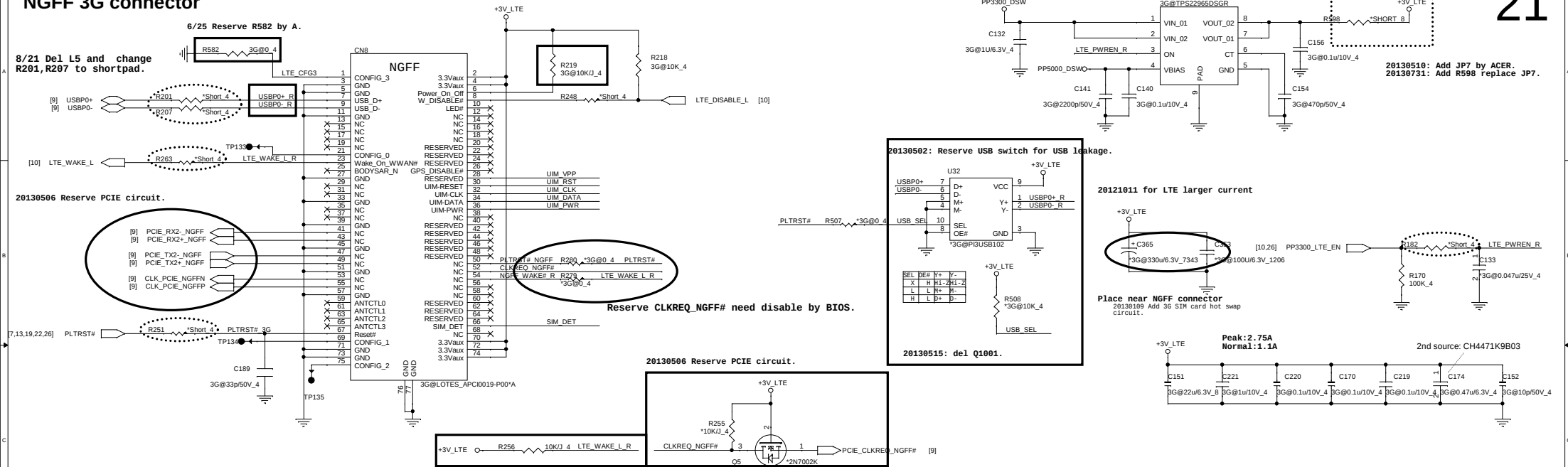


**Quanta Computer Inc.**
PROJECT : ZHN
HDMI

Size	Document Number	Rev
		3B
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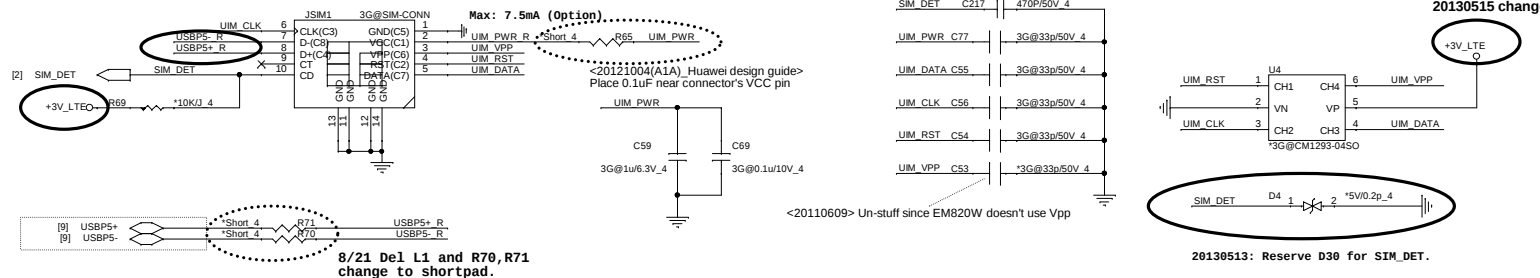
NGFF 3G connector



MultiMedia SIM (MNC)

<Layout Notes> Keep USIM signals max length within 8000mils.

5/14 Add R65



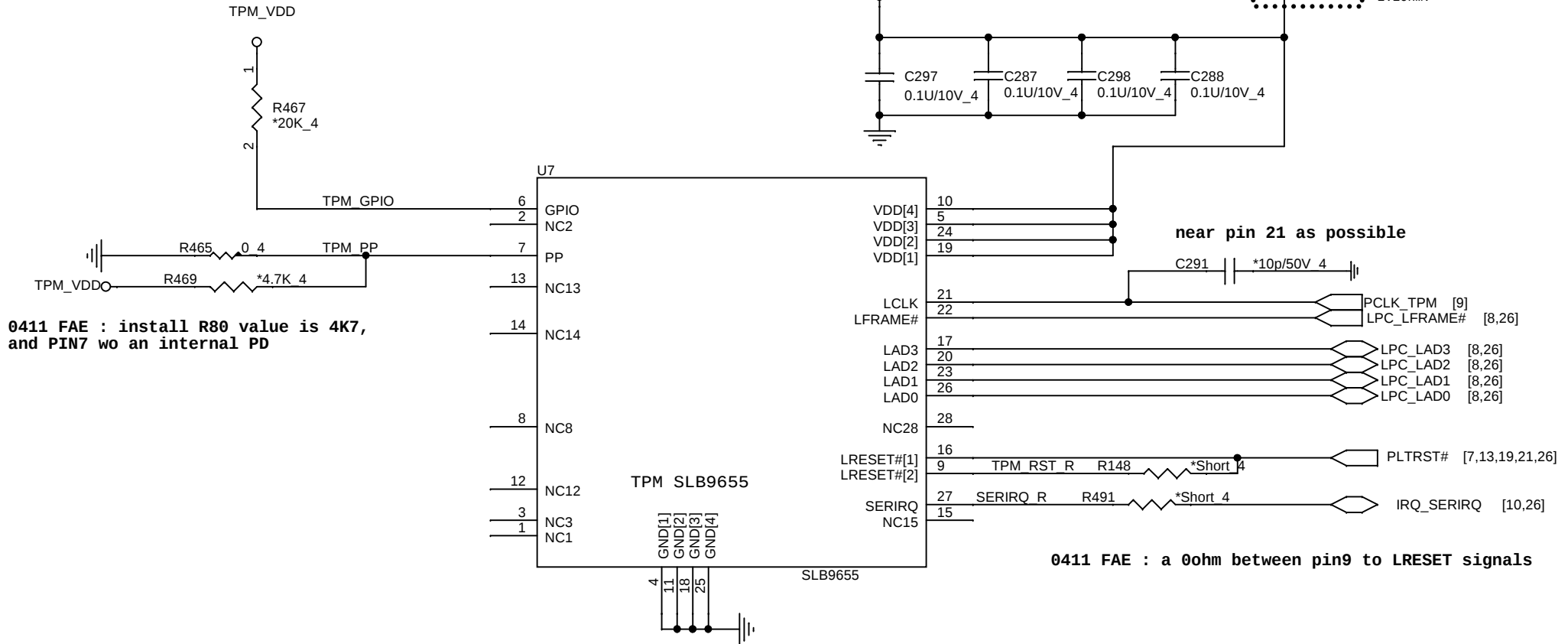
20130513: Reserve D30 for SIM_DET.

 Quanta Computer Inc. PROJECT : ZHN			
Size	Document Number	Rev	
	NGGF/ SIM conn	3B	
Date:	Monday, August 26, 2013	Sheet	21 of 39

TPM (TPM)

22

4 x100nF (place close to device VDD/GND pins)



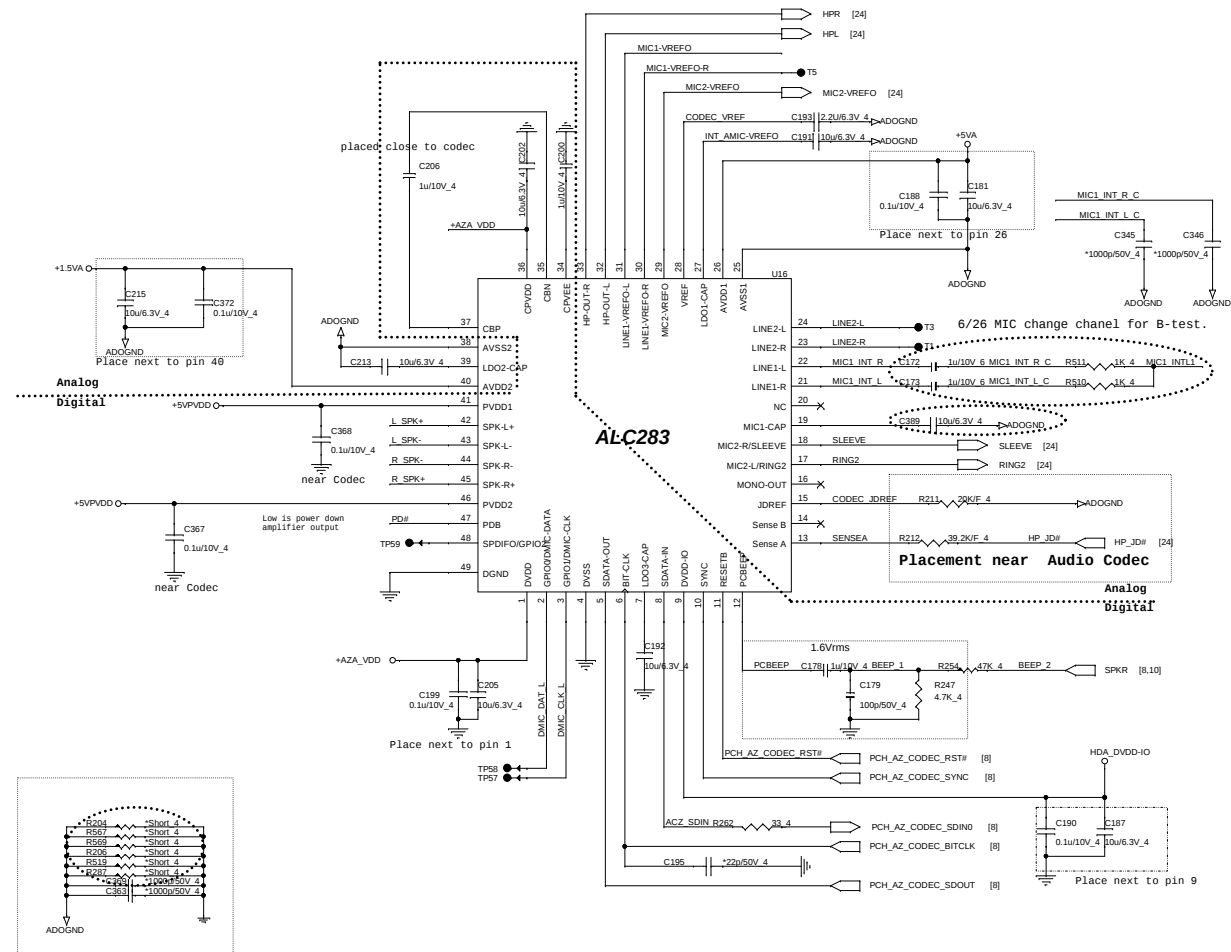
Quanta Computer Inc.

PROJECT : ZHN

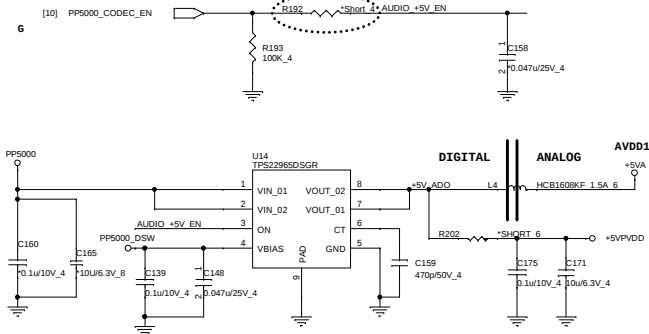
Size	Document Number	Rev
	TPM SLB9655 / LED	3B

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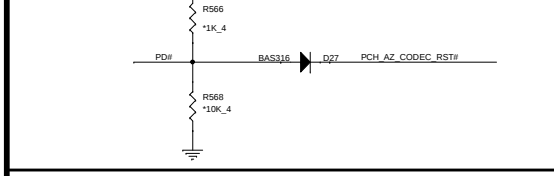
Codec(ADO)



Codec PWR 5V(ADO) 5/31 RevB Del R195, C161.

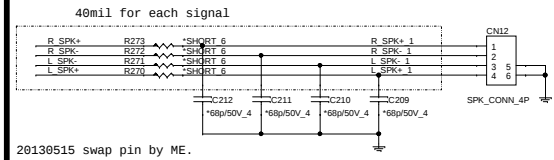


Mute(ADO)



Internal Speaker

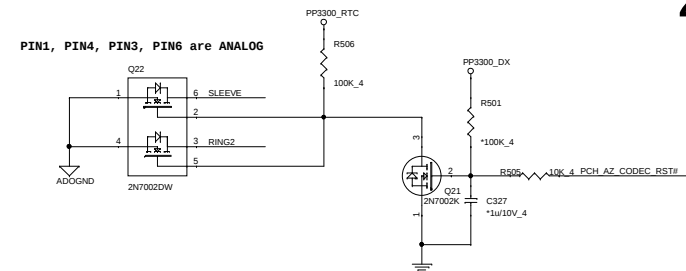
footprint 88266-040xx-xxx-4p-1



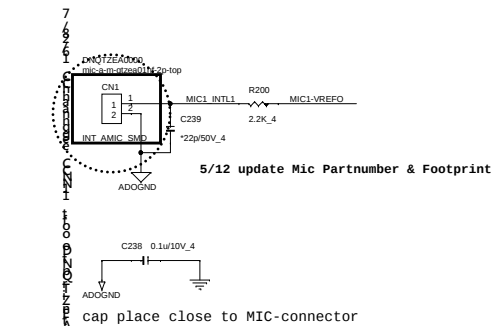
20130515 swap pin by ME.

Grounding circuit(ADO)

PIN1, PIN4, PIN3, PIN6 are ANALOG

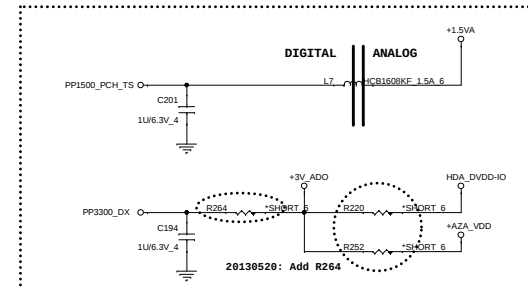


INT MIC array



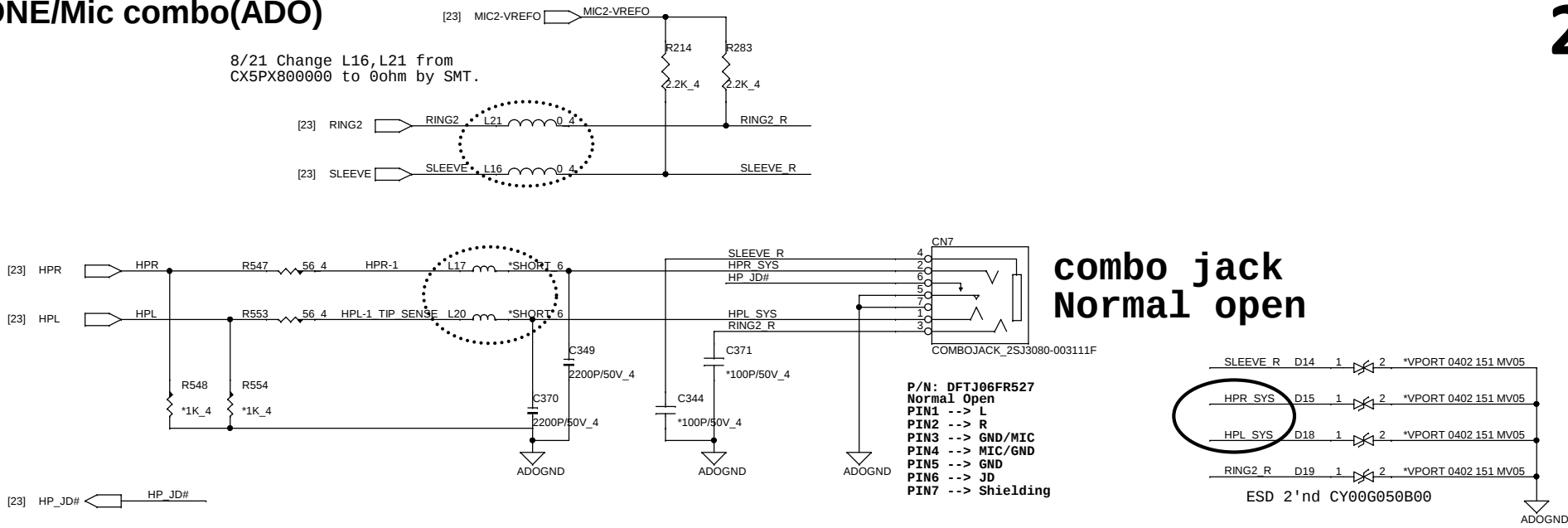
Codec PWR 3V/1.5V(ADO)

20130517 U13 remove, power source pass through to output.



HEADPHONE/Mic combo(ADO)

8/21 Change L16,L21 from CX5PX800000 to 0ohm by SMT.



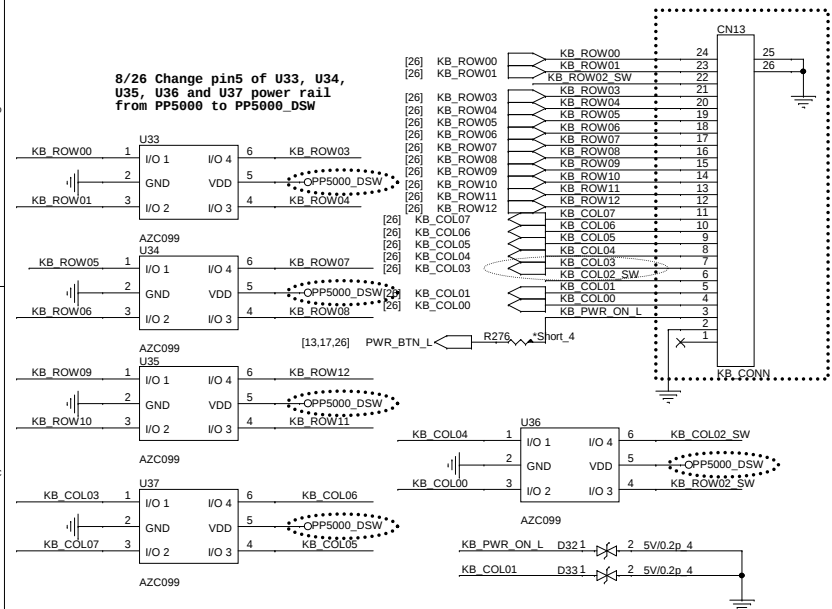


Quanta Computer Inc.
PROJECT : ZHN

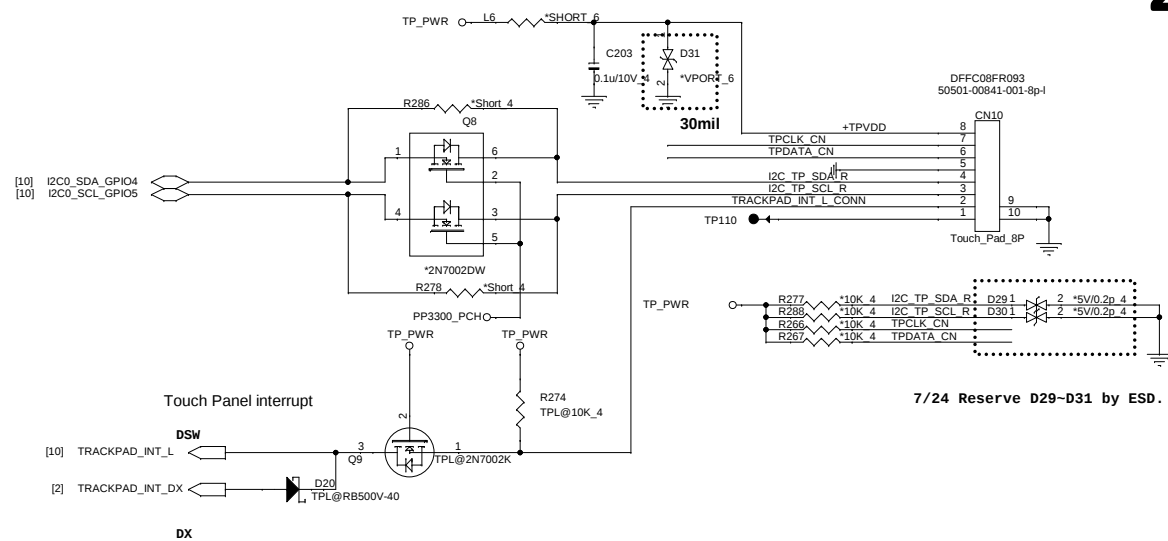
Size	Document Number	Rev
	Audio Headset SW	3B
Date:	Monday, August 26, 2013	Sheet 24 of 39

K/B (KBC)

8/22 DFFC24FR098
footprint 88502-2401-24P-L-SMT



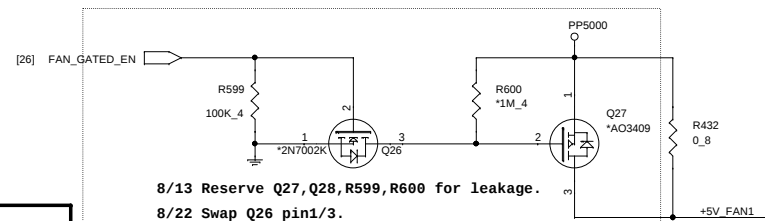
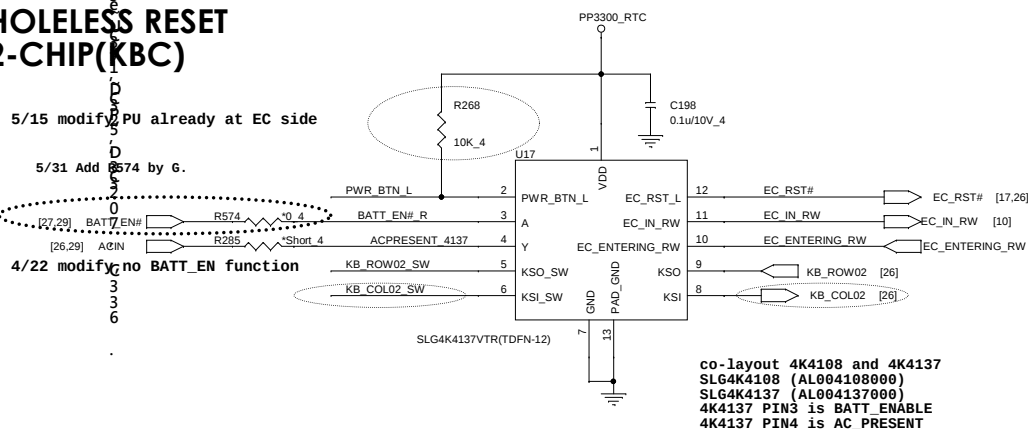
TOUCHPAD BOARD CONN (TPD)

HOLELESS RESET
2-CHIP(KBC)

5/15 modify CPU already at EC side

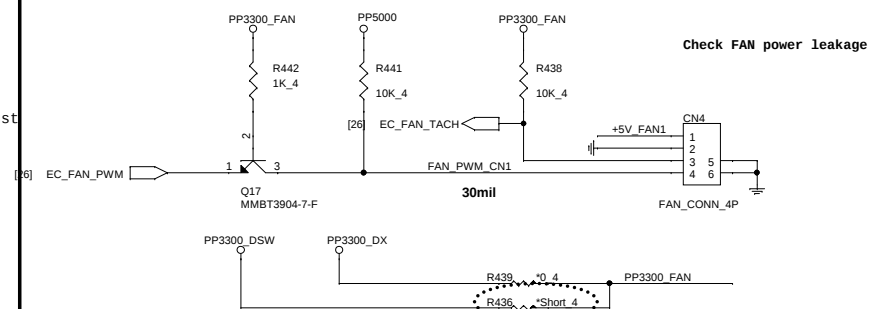
5/31 Add R574 by 6.

4/22 modify no BATT_EN function



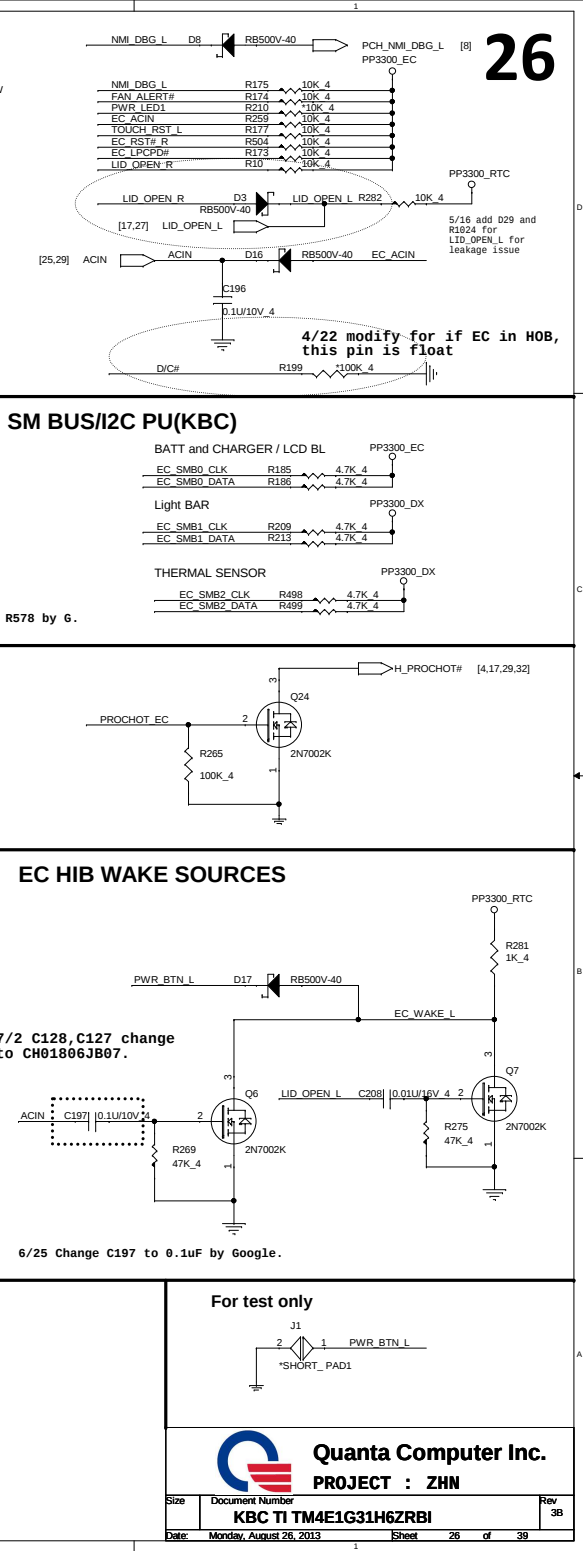
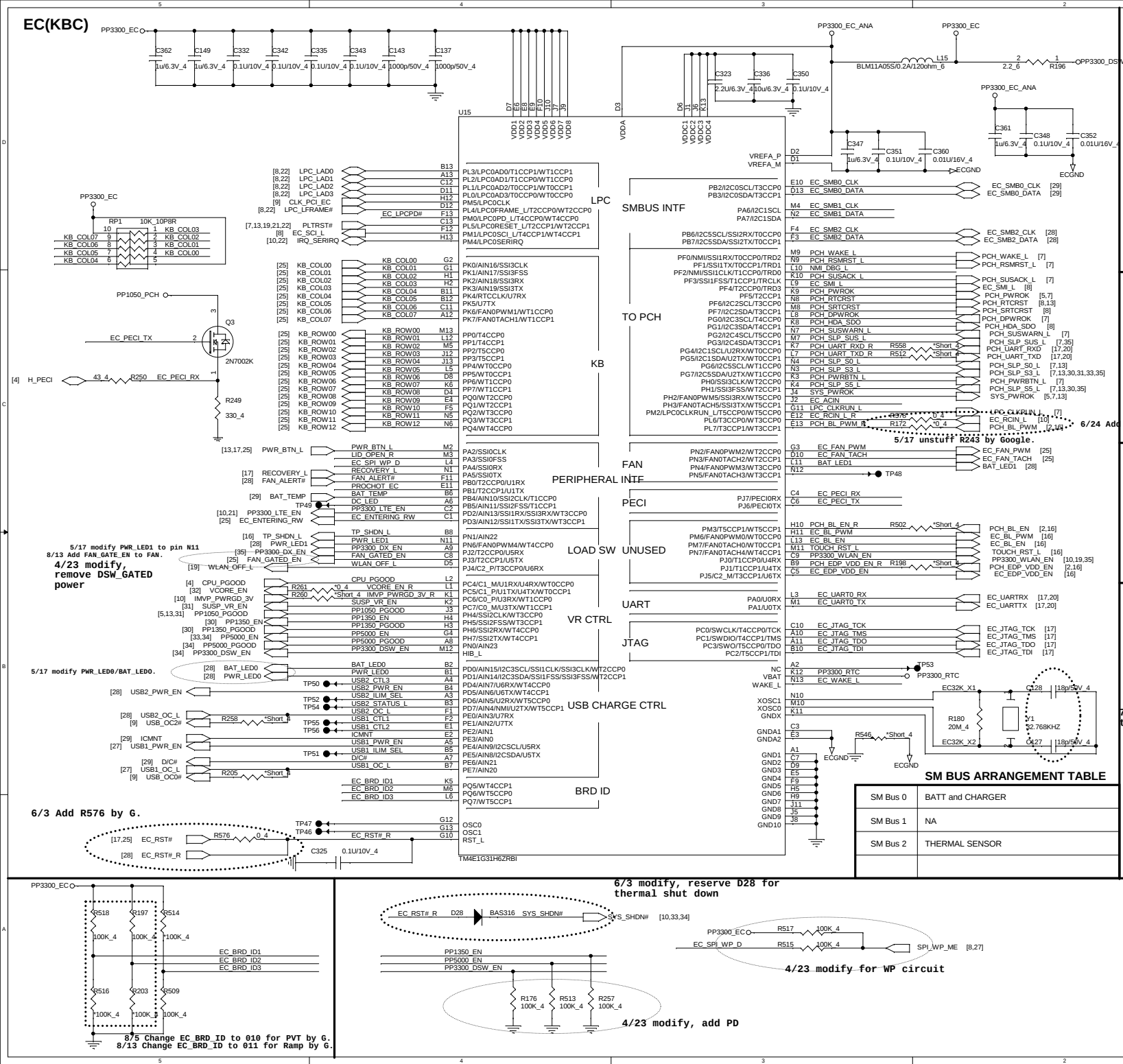
CPU FAN1 (THM)

Check pin define 0321
footprint 88266-040xx-xxx-4p-1

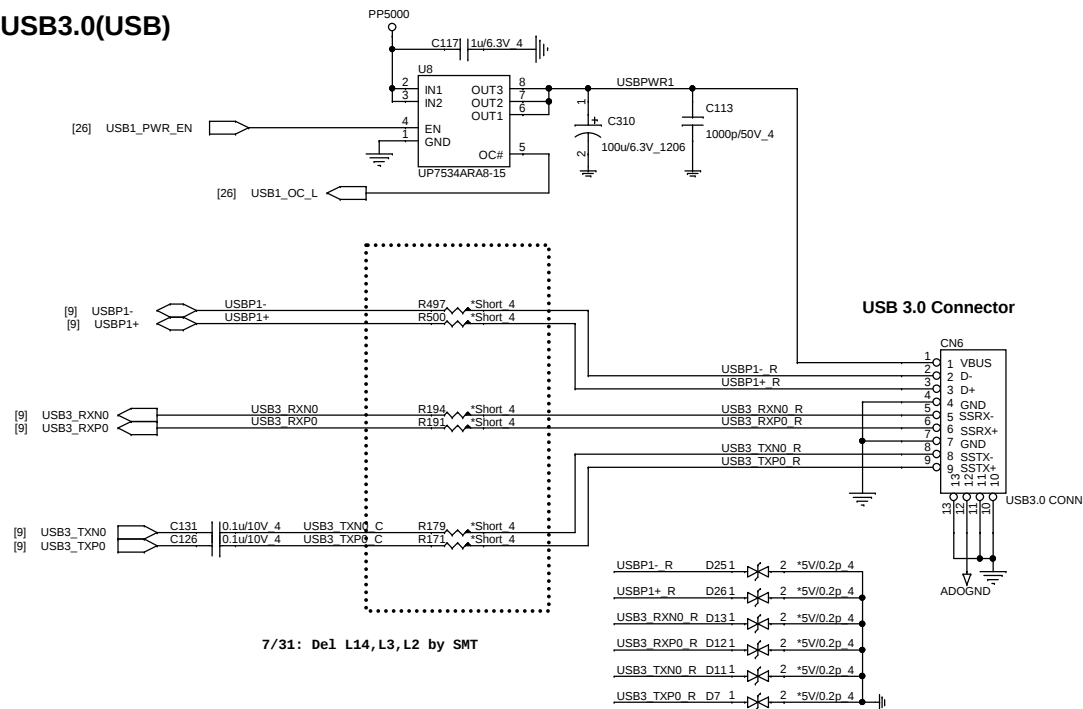


Quanta Computer Inc.
PROJECT : ZHN

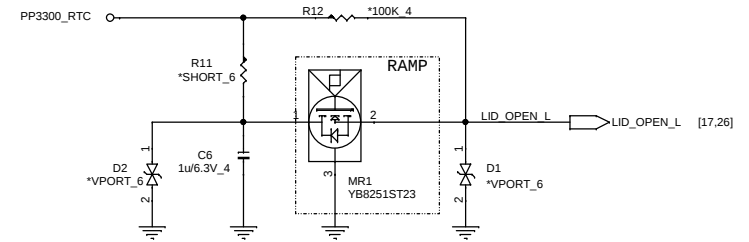
Size	Document Number	Rev
	KB/TP/FAN/HW Reset	38
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USB3.0(USB)



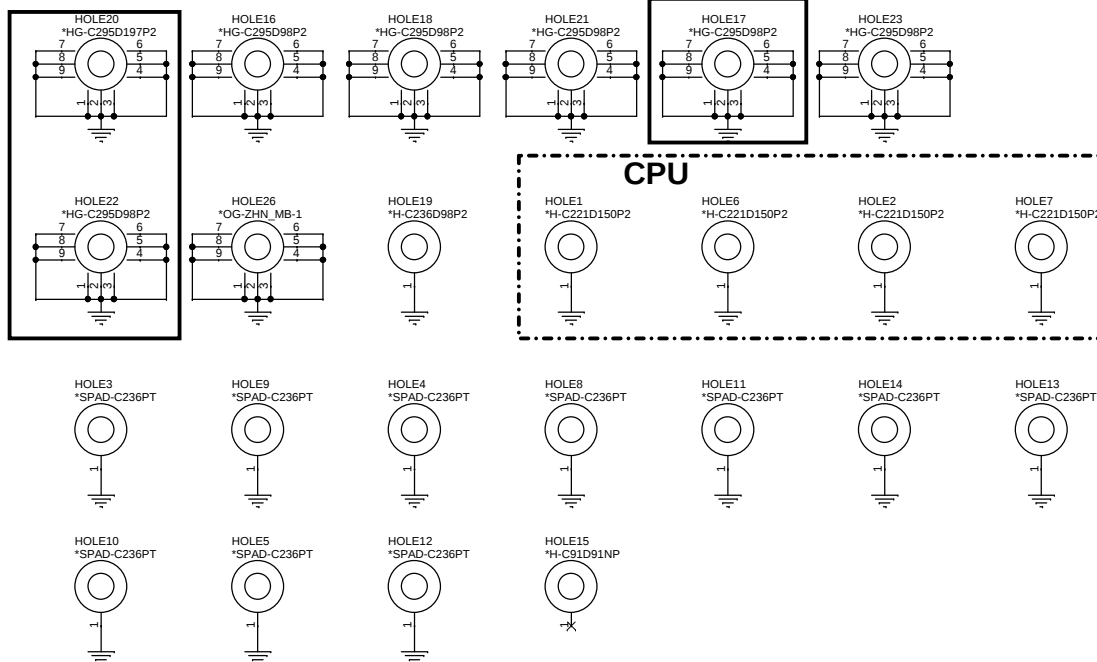
Lid Switch (HSR)



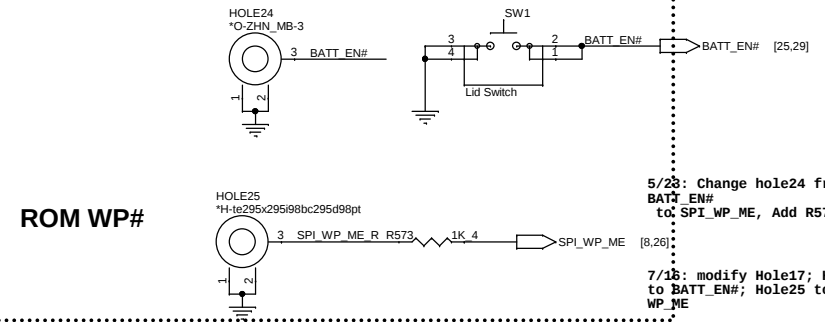
20130515 Add Hall IC by ME.

HOLE(OTH)

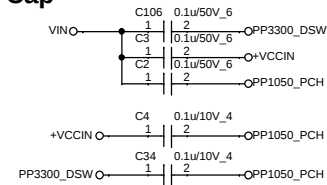
6/26 change footprint by ME.



BATT Enable short pad

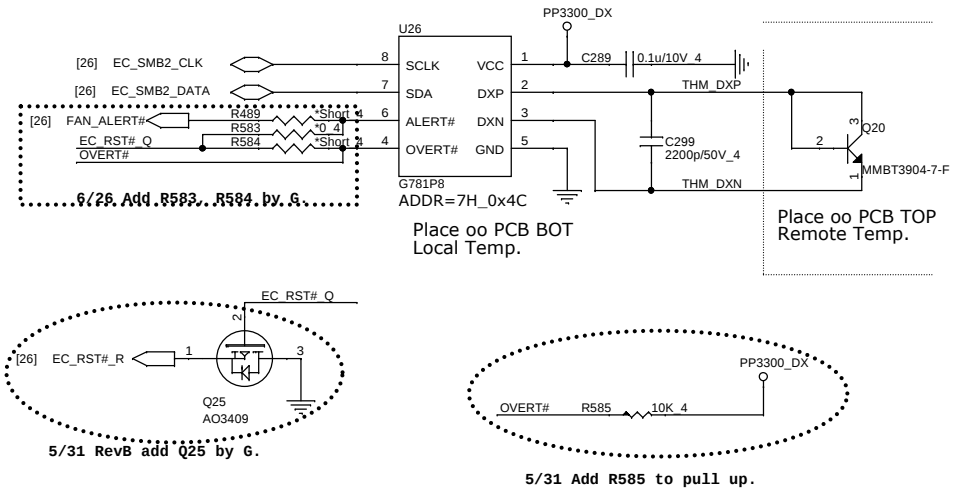


EMI Cap

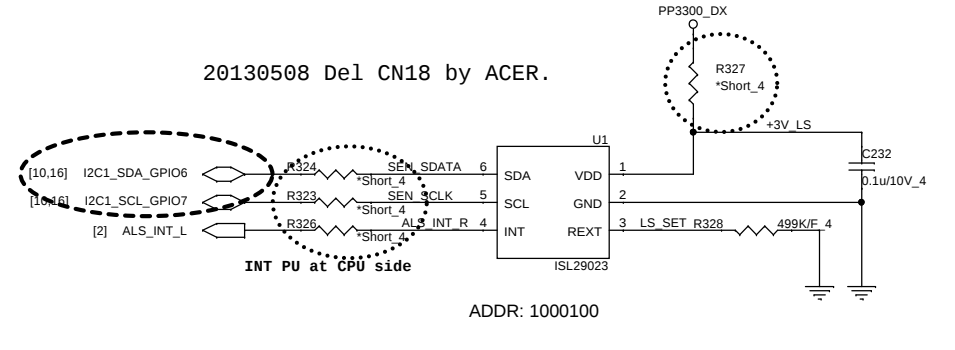


20130520: Add C6417, C6418, C6419, C6420, C6421

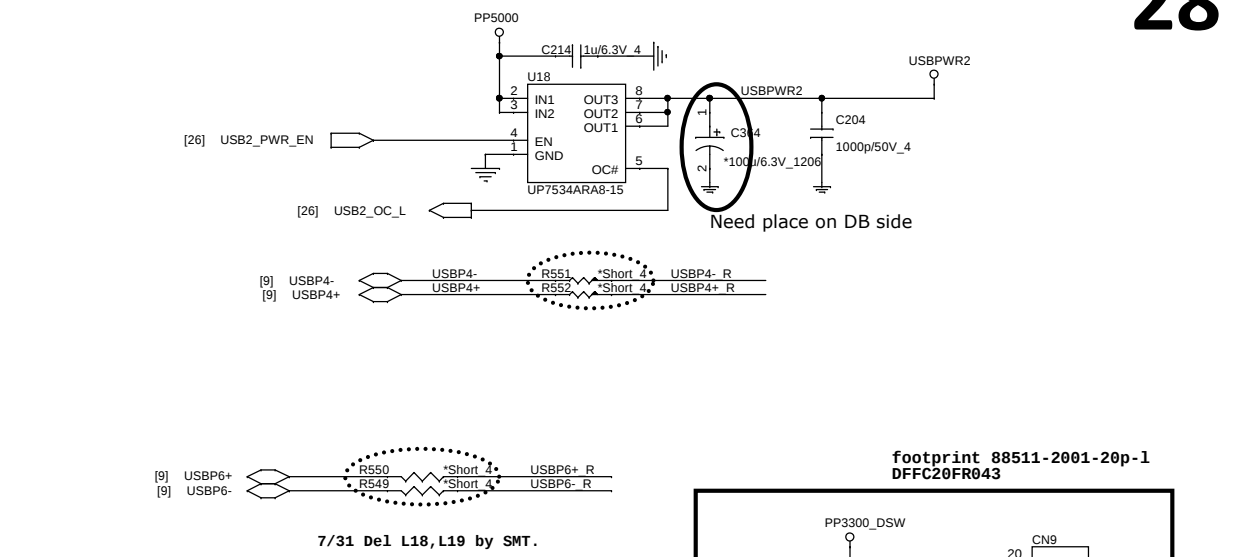
Thermal Sensor(THM)



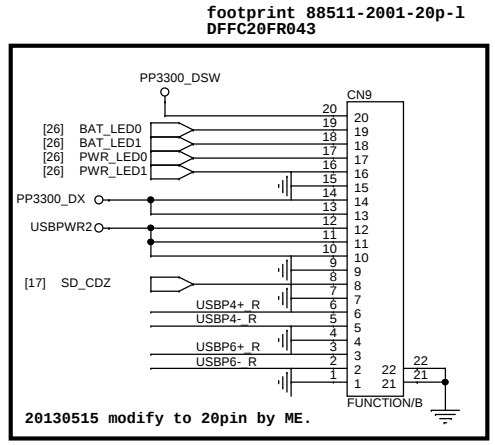
Light sensor & TP (SER)



FUNCTION DB

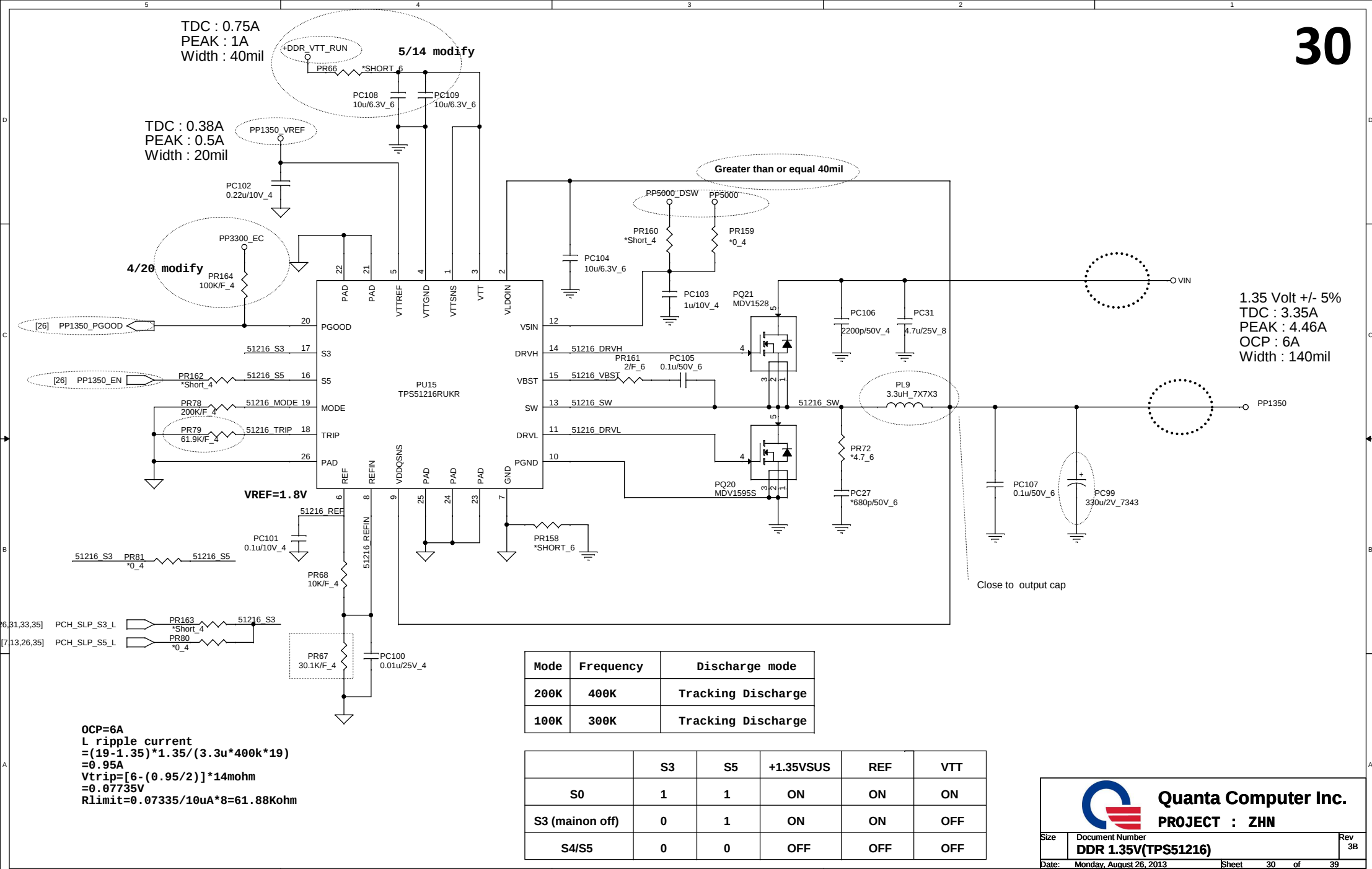


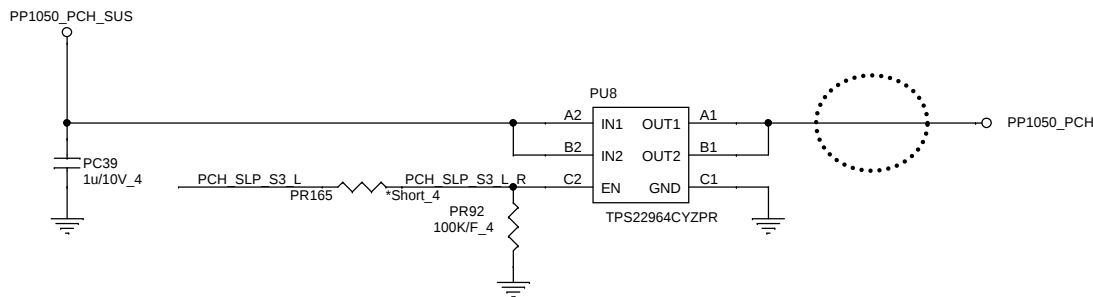
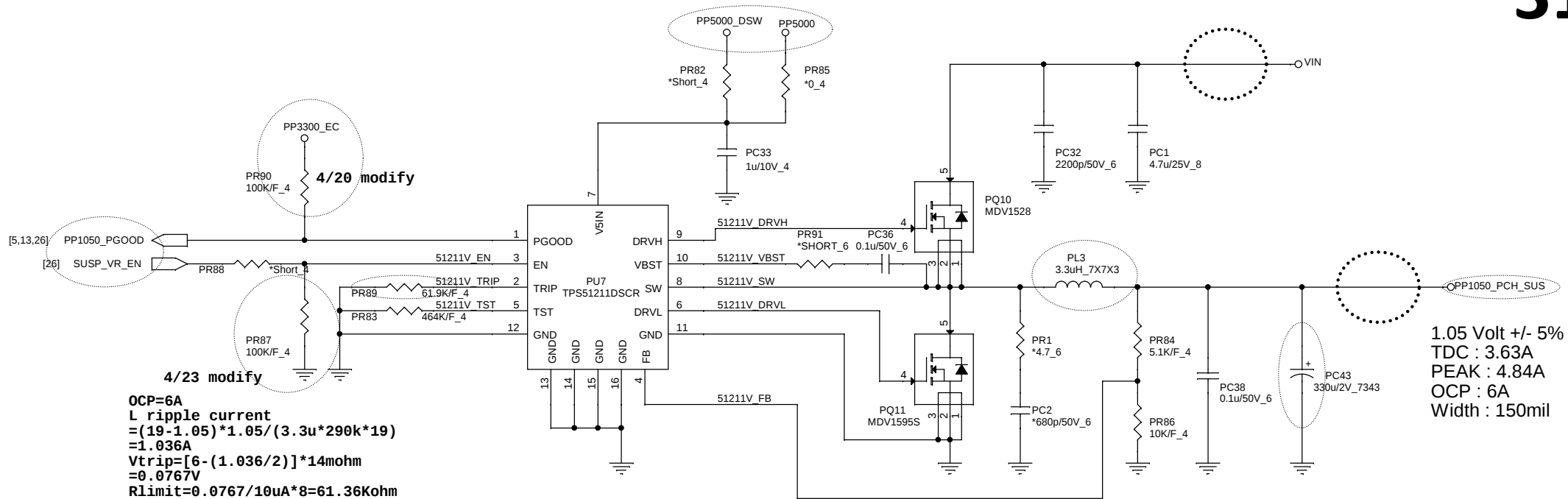
HSR	+3VPCU
	LID_OPEN_L
	GND
LED	+3VPCU
	LED x 4
	GND
USB	+3V x 2
	GND x 2
	USBP0+
	USBP0-
CR	CR_DET
	+3V x 2
	USBP6+
	USBP6-
	GND x 2



Quanta Computer Inc.
PROJECT : ZHN

Size	Document Number	Rev
	DB/ALS/Thermal sensor	3B
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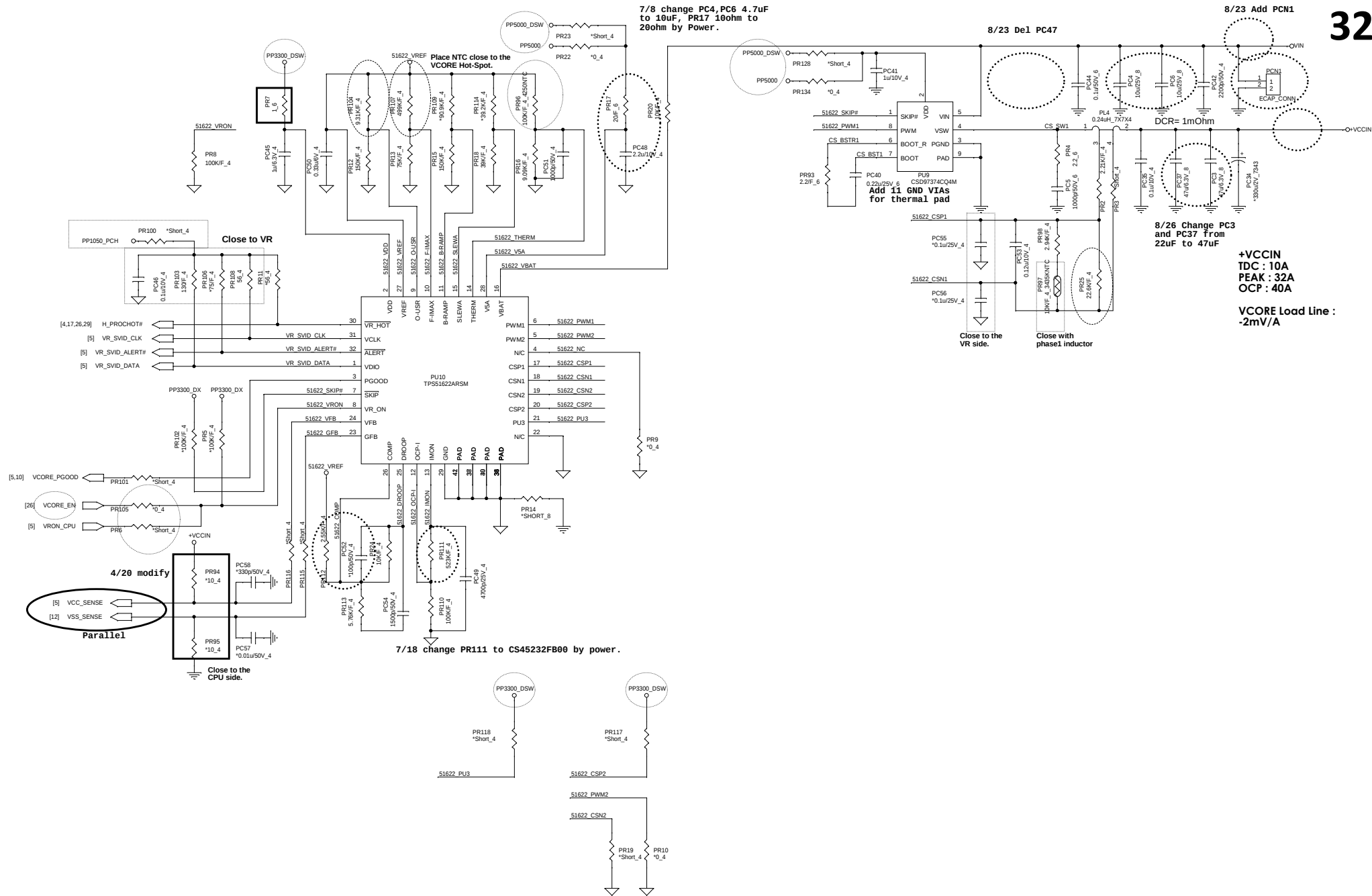


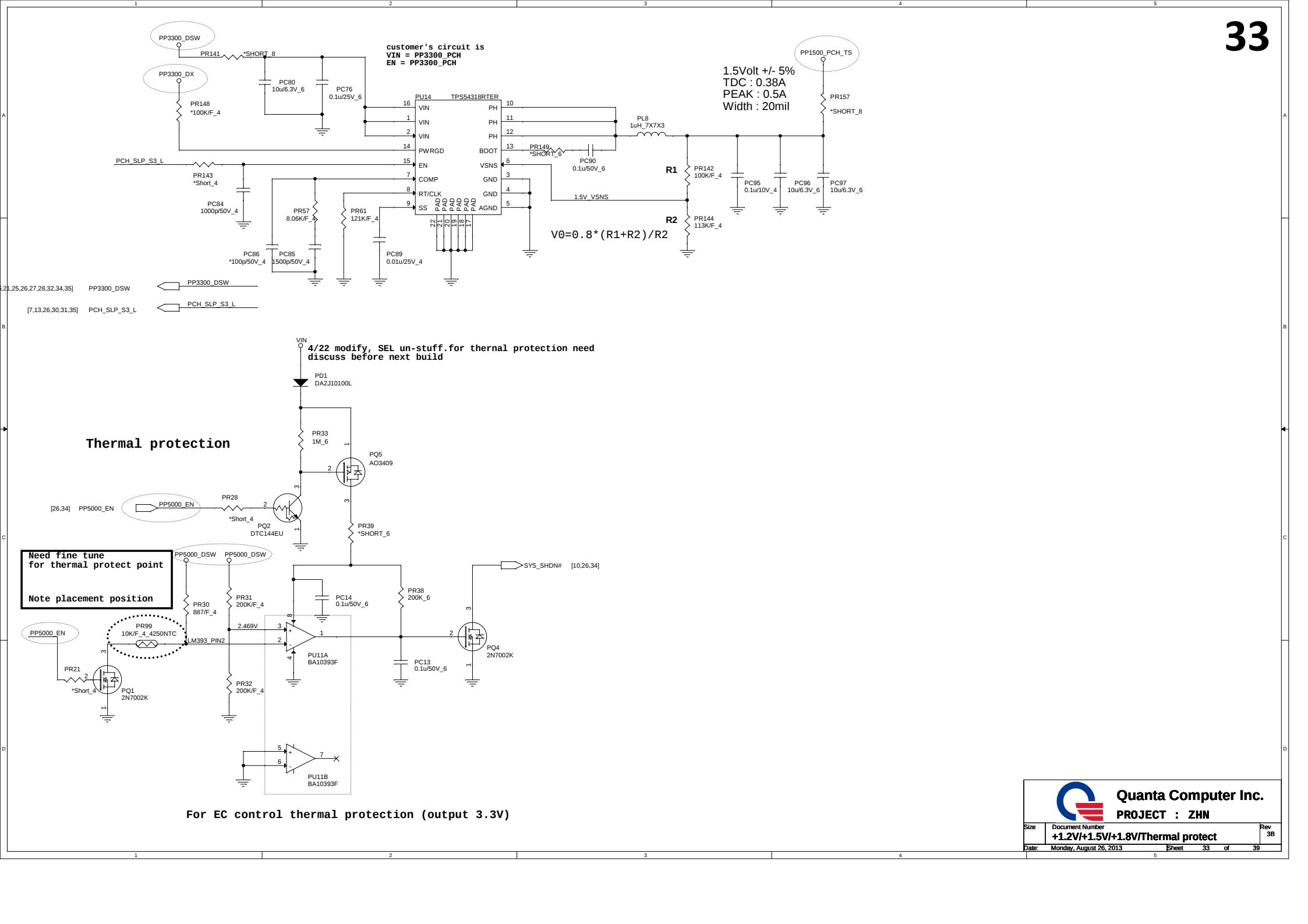


Quanta Computer Inc.
PROJECT : ZHN

Size	Document Number	Rev
	+1.05V(TPS51211)	3B

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33

customer's circuit is
VIN = PP3300_PCH
EN = PP3300_PCH

1.5Volt +/- 5%
TDC : 0.38A
PEAK : 0.5A
Width : 20mil

$V0 = 0.8 * (R1 + R2) / R2$

PP3300_DSW
PP3300_DX
PP3300_PCH
PP1500_PCH_TS

PCH_SLP_S3_L

PP3300_DSW
PCH_SLP_S3_L

4/22 modify, SEL un-stuff.for thermal protection need discuss before next build

Thermal protection

Need fine tune for thermal protect point
Note placement position

PP5000_EN
PP5000_DSW
PP5000_DSW
PP5000_EN
PP5000_EN

PR28
PR30
PR31
PR32
PR33
PR38
PR39

PQ2
PQ1
PQ4
PQ5

PC14
PC13

LM393_PIN2
PU11A
PU11B

2.469V

SYS_SHDN#

For EC control thermal protection (output 3.3V)

 Quanta Computer Inc. PROJECT : ZHN		Rev 3B
Size	Document Number	
+1.2V/+1.5V/+1.8V/Thermal protect		
Date:	Monday, August 26, 2013	Sheet 33 of 39

33

customer's circuit is
VIN = PP3300_PCH
EN = PP3300_PCH

1.5Volt +/- 5%
TDC : 0.38A
PEAK : 0.5A
Width : 20mil

$V0 = 0.8 * (R1 + R2) / R2$

PP3300_DSW

PCH_SLP_S3_L

Thermal protection

4/22 modify, SEL un-stuff.for thermal protection need discuss before next build

Need fine tune for thermal protect point
Note placement position

For EC control thermal protection (output 3.3V)

Quanta Computer Inc.
PROJECT : ZHN

Size	Document Number	Rev
	+1.2V/+1.5V/+1.8V/Thermal protect	3B
Date:	Monday, August 26, 2013	Sheet 33 of 39

33

customer's circuit is
VIN = PP3300_PCH
EN = PP3300_PCH

1.5Volt +/- 5%
TDC : 0.38A
PEAK : 0.5A
Width : 20mil

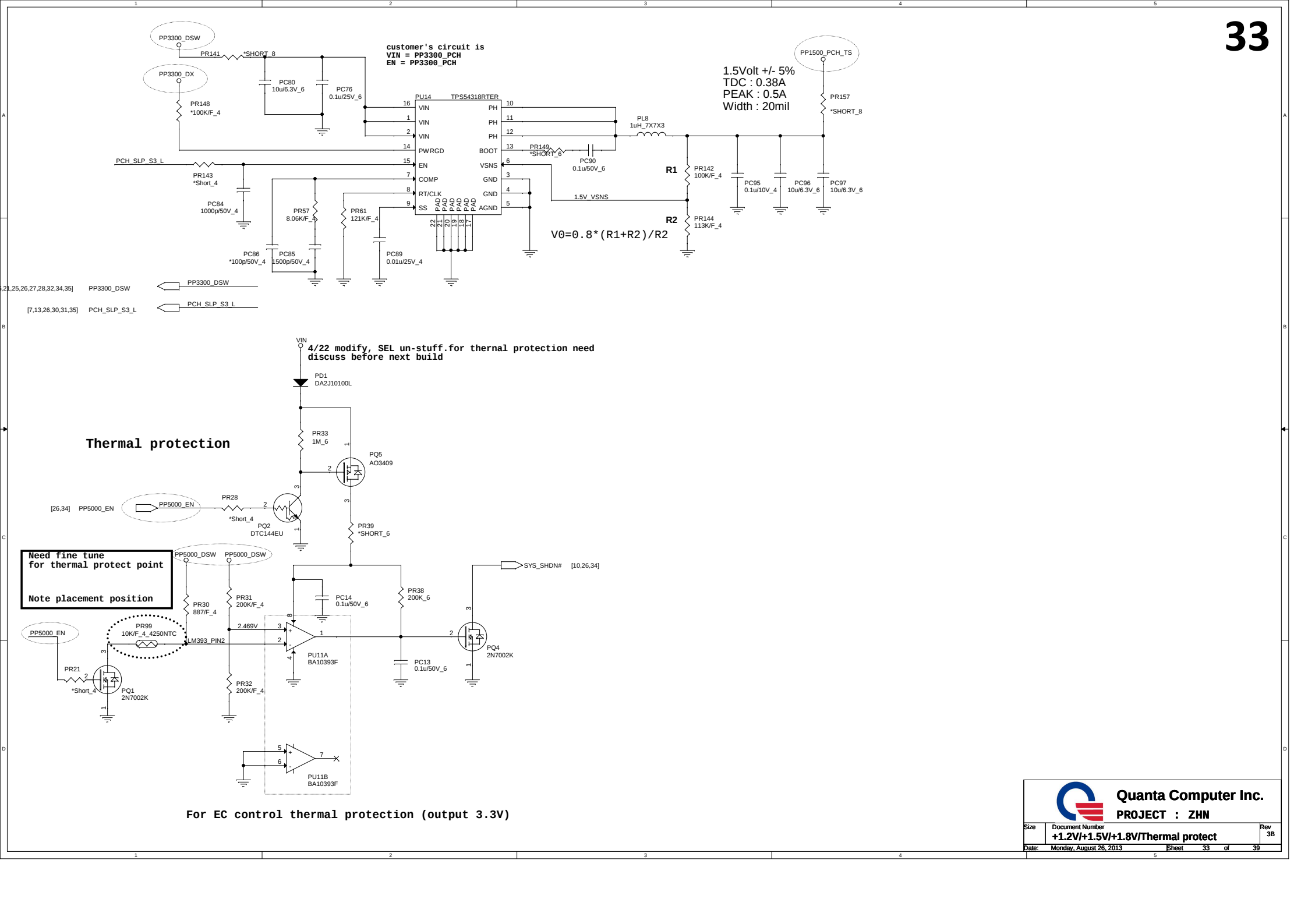
$V0 = 0.8 * (R1 + R2) / R2$

4/22 modify, SEL un-stuff.for thermal protection need discuss before next build

Thermal protection

Need fine tune for thermal protect point
Note placement position

For EC control thermal protection (output 3.3V)



33

customer's circuit is
VIN = PP3300_PCH
EN = PP3300_PCH

1.5Volt +/- 5%
TDC : 0.38A
PEAK : 0.5A
Width : 20mil

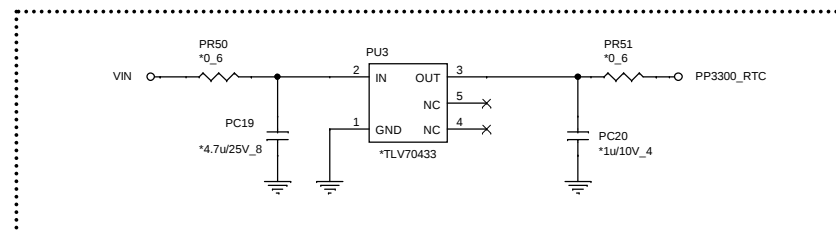
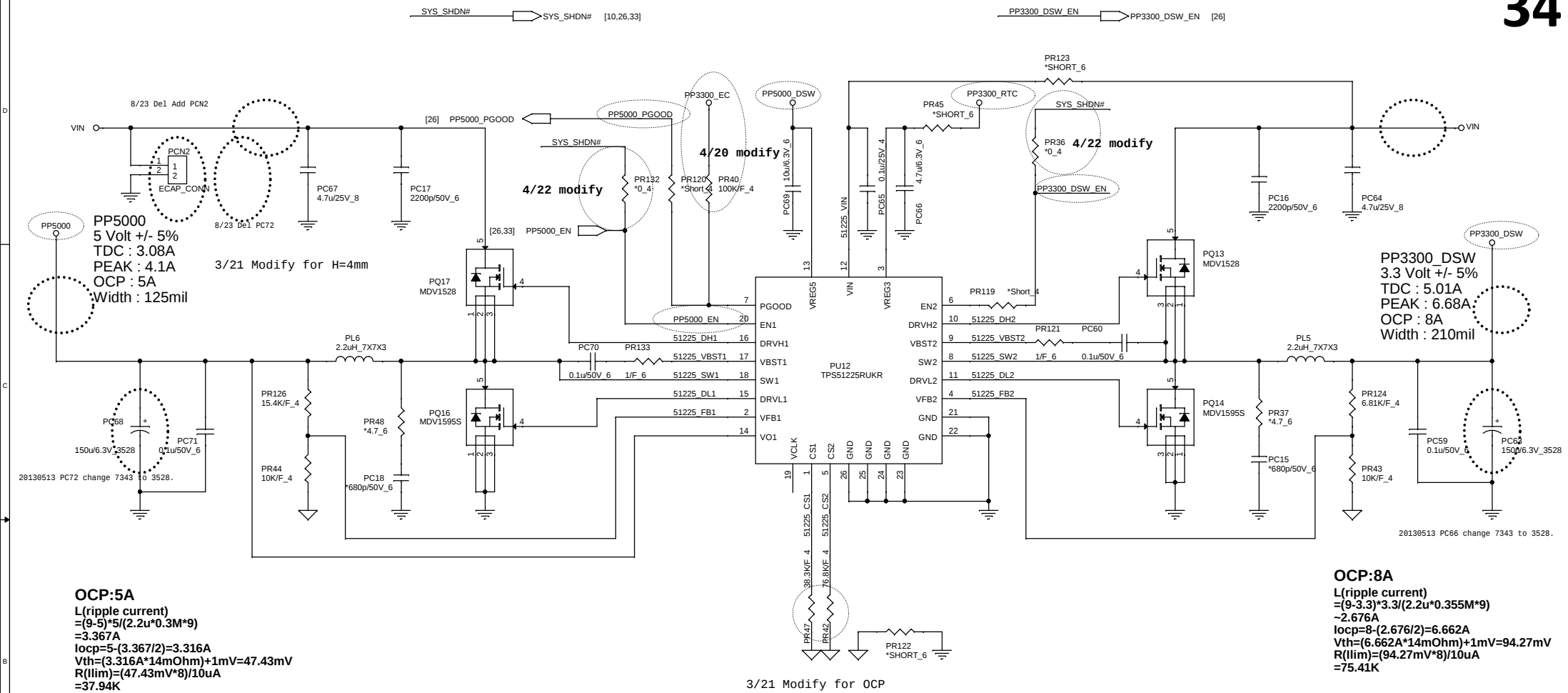
$V0 = 0.8 * (R1 + R2) / R2$

4/22 modify, SEL un-stuff.for thermal protection need discuss before next build

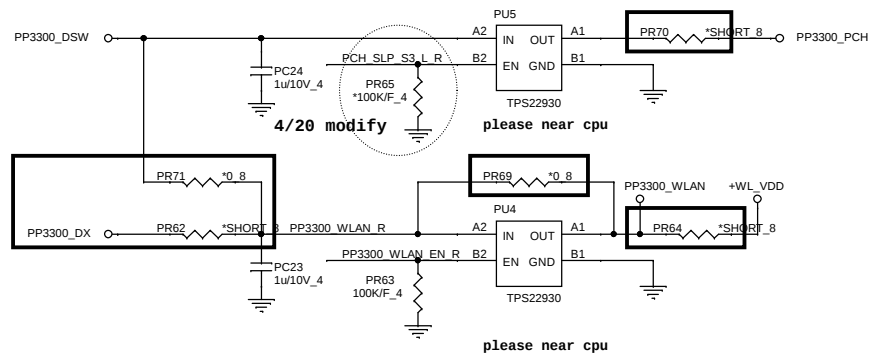
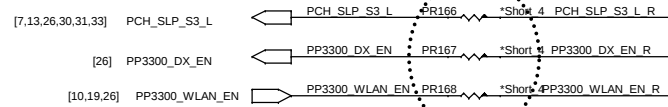
Thermal protection

Need fine tune for thermal protect point
Note placement position

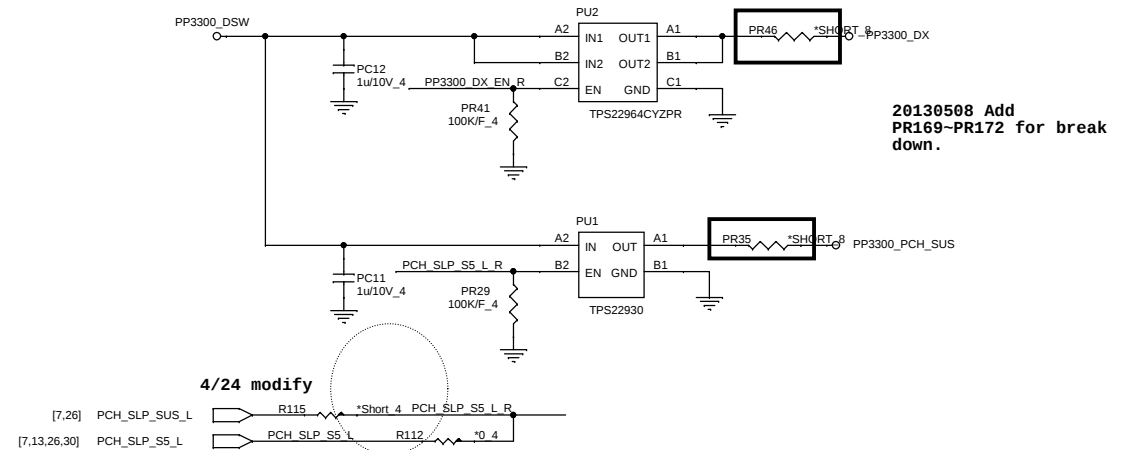
For EC control thermal protection (output 3.3V)

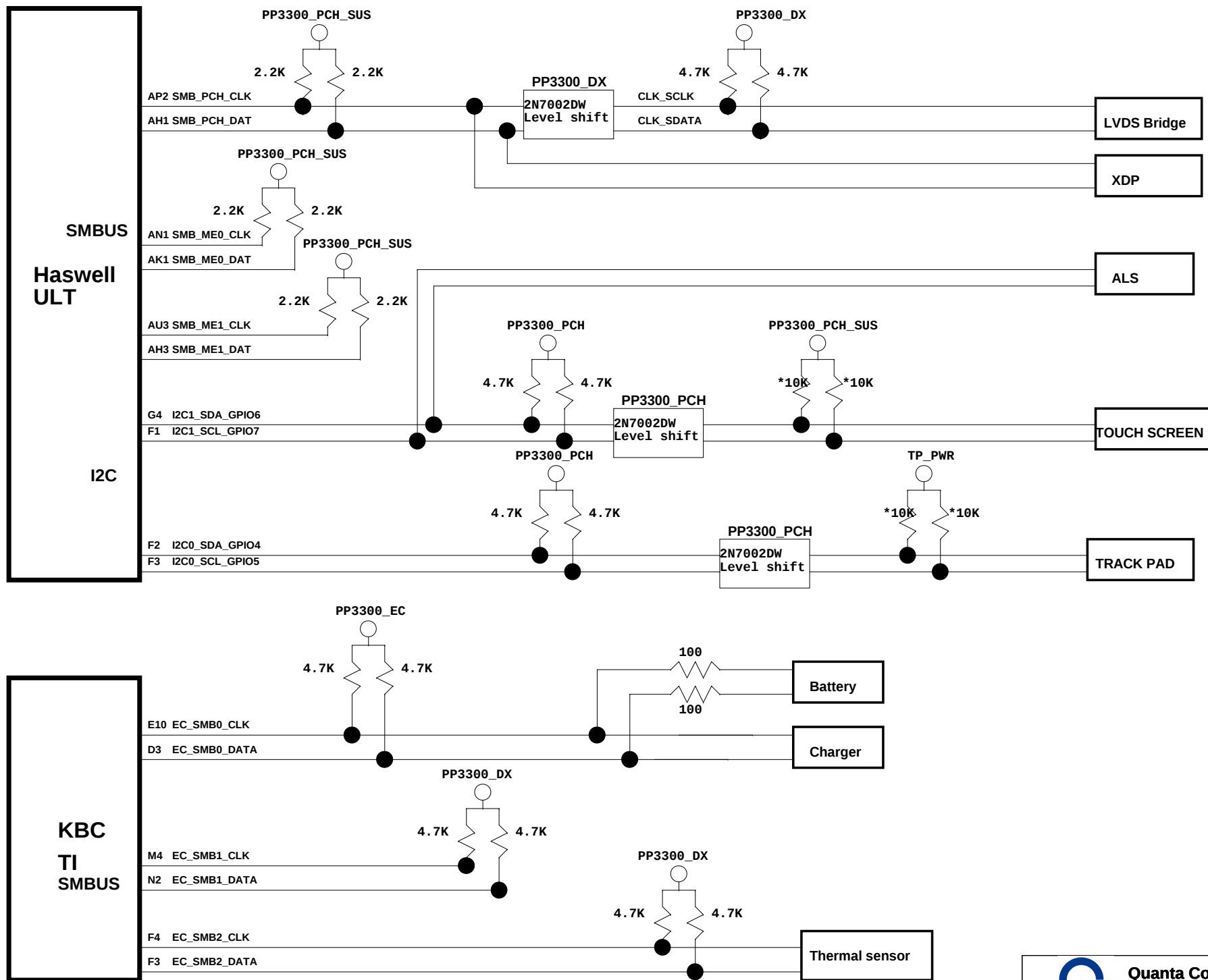


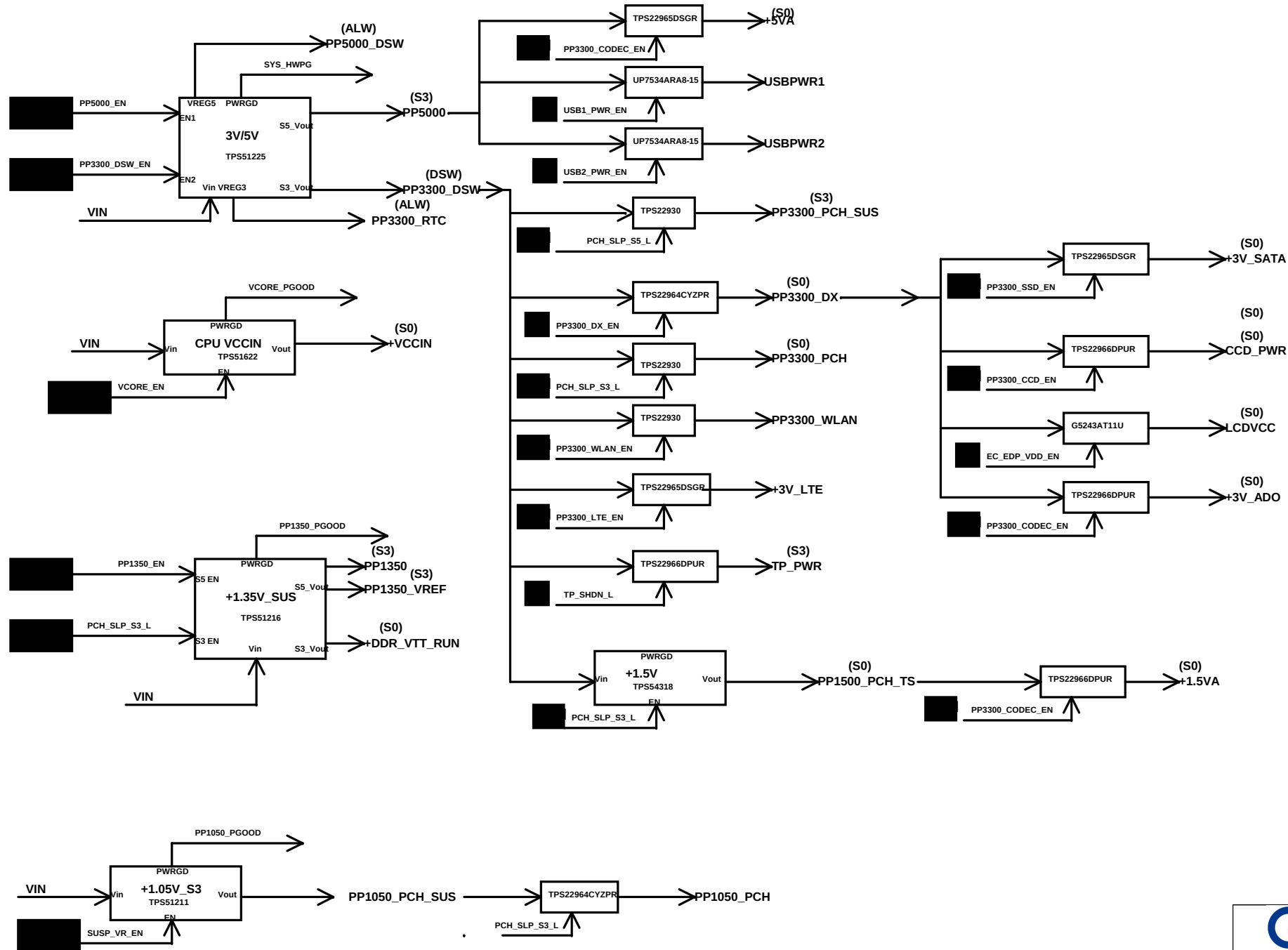
6/23 Add PR166~168 for debug.



20130517 Page35 Add PR174 & reserve PR175,PR176 to input pwr PU4 by ACER.







Model	Version	CHANGE LIST	
Benetton	1A	20130428 Page 21: Change net name USBP0_ R to USBP0_ R, USBP0_ R, USBP0_ R to USBP0_ R	
		20130502 Page21: Reserve USB switch USB0R, Q100,R1000 for USB leakage.	
		20130502 Page31 Del +LVB_SSD, +L2V_SSD power circuit.	
		20130502 Page11 Del CNI for XDP debug.	
		20130502 Page17 Del RVN3 Del EEPROM Mode strapng R163,R162,R176,R177.	
		20130501 Page16 Del DMIC circuit R421,R422,C315,C316.	
		20130501 Page2224 Del DMIC & Auto switch by Google.	
		20130501 Page20 Add Cap C6410-C6411.	
		20130501 Page29 Change P11 and P12 footprint.	
		20130501 Page9 Add CSMP and CLK_PCL LPC with R1004.	
20130506 Page23 Change AMIC(CN17) footprint to mic-kec22424612p.			
20130506 Page21 Reserve PCB circuit & USB0 pin5 connect to GND & change JSIM1footprint to sim-c01x-3-14p-out by ME.			
20130506 Page9 Reserve PCB circuit			
20130507 Page16 Add R1014 for PU DEVSLP0.			
20130507 Change connector footprint by ME.			
20130508 Page 29 Change connector P11 footprint by ME, add PLR,PL9 for EMI.			
20130508 Page21 Del CN18 by ACER.			
20130508 Page35 Add PR100-PR172 for power breakdown.			
20130509 Page19 Del R100,R102,R104, R105 by ACER.			
20130509 Page25: change R31-con CN13 to 24pin first by ACER.			
20130510 Page27 Add Hole and SWR for BATT_EN0.			
20130510 Page21: Add P911 by ACER.			
20130510 Page28: Add R1015.			
20130510 Page25:change R31-con CN13 to 24pin first by ACER.			
20130510 Page31: Add JP12.			
20130511 Page34: change PC64,PC72 from 7143 to 3528.			
20130513 Page21: Reserve D10 for SDR_DET.			
20130513 Page28: Change CN2 from 28 to 24 pins for LEDIR.			
20130513 Page22: Del RS,R7,LED1, move to LEDIR.			
20130513 Page21: Reserve NXP-external R1016-R1018.			
20130514 Page21 Add R1020.			
20130514 Page21 Add PR173.			
20130514 Page25: swap CN13 pin define.			
20130515 Page23: swap CN8 pin define by ME.			
20130515 Page27: Add HS41 IC by ME.			
20130515 Page28: change CN2 from 24 to 20pins.			
20130516 Page21: add diode D29 and R1024 for L1D_OPEN_1 for leakage issue			
20130516 Page16 add R1023 by Atmel.			
20130517 Page25: swap CN12 pin define by ME.			
20130517 Page16: change L4 solution by ACER.			
20130517 Page28 USB remove , noSATA power connect to PP3300_DX.			
20130517 Page23 U13 remove, power source pin through to output.			
20130517 Page25: Add PR174 & reserve PR175,PR176 to input pair of P14 by ACER.			
20130517 Page28: net Bat_LED1-->(pin name) L116, PWRLED1-->N11; Battery LED0-->B, PWRLLED0-->B1			
20130517 Page25: U13 pin L-->HW02; pin 6-->C0L3 (113key)			
20130517 Page16: stuff BS2,unstuff R100 & R243.			
20130520 Page21 Add R1025			
20130520 Page21 Remove +V3_ATC interseet			
20130520 Page14 RemoveRemove +SMDDR_VREF_DQ0 interseet			
20130520 Page15 RemoveRemove +SMDDR_VREF_DQ1 interseet			
20130520 Page11 Remove +V3_BDX, L5DX, L8DX_AUDIO interseet			
20130520 Page19 Remove +V1_BDS, MPL1,OPT interseet			
20130520 Page27: Add C447,C449,C449,C449,C449,C449			
20130520 Page27 Add Add USBPWR2 at CN2.10			
20130521 Page21 Add R1026 for PU GPIO20.			
20130521 Page11 Change C143 from 0.1uF to 1uF; C78 1uF to 0.1uF; R103 shortpad to Behn; C200&C204 stuff; C274&C206 47uF to 22uF .			
20130522 Page28 Change CN13 footprint to micpin-8000-1001-52p.			
20130522 Page25: 12 Change U22 P10 to A100-HV-T01.			
20130522 Page28 Change CN15 P10 to DFHS12FR161.			
20130522 Page21 modify all component to ZCH0value & Hynix Ram P10 for BOM.			
20130522 Remove from 0222-2000.			
20130522 Page25: stuff R206,R205 by Google.			
20130522 Page16: change R103,R102 from 47K to 2.2K by TS suggestion & stuff Q23.			
20130523 Page27: change Change hole24 from BATT_EN0 to SPI_WP_ME, and add R573			
20130523 Page27 R74 on-stuff by L.			
20130523 Page13 R72, R300, C230, C231, U19, U22 stuff by L.			
20130523 Page4 R29 on-stuff.			
2A		20130531 Page28 Add Q25 to EC_RSTB by G.	
		20130531 Page23 Del R195, C181.	
		20130531 Page19 Reserve R100 and R575 to PU PP2300_PCH_SUS.	
		20130603 Page26 Add R576, reserve D28 for thermal shut down	
		20130603 Page13 Add TP111-TP122 by ICT	
		20130613 Page19 change R103,R102 to 47K for ALS abnormal.	
		20130613 Page16: stuff R425 for EDP.	
		20130616 Page28: change CN14 from mSATA to NGFF type and add C383.	
		20130617 Page18 change CN5 footprint from hfsmd-B0103-1121-13p-fds to hfsmd-B0103-1121-13p-fds-unt.	
		20130617 Page27: change CN6 footprint from sub-SMD5-09002-001-5p to sub-SMD5-09002-001-5p-unt.	
		20130618 Page21 Del RTC circuit (D9, R100,RTT1,Q2,R10,R102,R104,R106) by A.	
		20130618 Page28 Del R132.	
		20130620 Page21 Change R479 to 2.2ohm.	
		20130620 Page28 6/20 Add R577 by Kingston SSD; change CN14 to DFHS12FR003 by ME.	
		20130620 Del all Offpage of power signals in all page.	
		20130621 Add C384-C388 by Intel D0R layer.	
		20130621 Change CN1 to D9000024000 by ME.	
		20130624 Page 36 Add R578 for B-test by G.	
		20130624 Page 10 Modify RAM ID table & connect DEVSLP0 to NGFF SSD for B-test by G.	
		20130624 Page 35 Add PR106-108 for B-test debug.	
		20130624 Remove PP5000, ALN to PP5000, DEVN by G.	
		20130625 Page27 R74 stuff by G.	
		20130625 Page28 Change C197 to 0.1uF; Change EC_BRD_ID to 001 by G.	
		20130625 Page29 Change PMS2 to 47Kohm by G.	
		20130625 Page21 Add TP127-TP132 for XDP by Intel.	
		20130625 Page28 Add R580-R581 by Kingston SSD.	
		20130625 Page21 Reserve R582 by G.	
		20130625 Page21 Change MIC, channel from pin19/20 to pin21/22, and add cap C389 by vendor.	
		20130626 Page19 Modify RT_JFN path, stuff R161.	
		20130626 Page21 Add TP133-135 by A.	
		20130626 Page28 Add R583,R584 by G.	
		20130626 Page27 Change Hole2,22 footprint by ME.	
		20130626 Page21 Change C27&C286 to 15uF by crystal.	
		20130626 Page28 Change C127,C128 to 10pF by crystal.	
		20130626 Page21 Change P050 to C1310&S02 to C-test by Power.	
		20130705 Page18 Change R142,R134,R127,R119,R113,R129,R116,R111 from 680 to 470ohm; unstuff R114,R122,R133,R457 by HDMI EA unt.	
20130709 Page12 change PC4,PC6 from 47uF to 10uF, PR17 from 10ohm to 20ohm by Power.			
3A		20130711 Page11 R40 connection change to PP3300_PCH by leakage.	
		20130711 Page25 unstuff R574 by G.	
		20130716 Page14 unstuff PCL,PLC,PC20 by power.	
		20130716 Page27 modify Hole17 to GND; Hole24 to BATT_EN0; Hole25 to SPI_WP_ME by G.	
		20130718 Page13 Change R1111 to C45&C39 800 by power.	
		20130718 Page11 unstuff U19,U22 by ICT.	
		20130722 Page12 modify PU10,PLC,PC17,PC4,PC1,PC48,PR10,R111,PR112, unstuff PC32 by power.	
		20130722 Page21 Change SW2 to H by ME usage.	
		20130723 Page28 Change EC_BRD_ID from 001 to 010(unstuff R197,R516; unstuff R201,R518).	
		20130724 Page22 Reserve D20-D31 by ESD.	
		20130724 Page29-35 Del JP and change Behn to shortpad.	
		20130724 Page16 Del colayout L12 by SMT.	
		20130729 Page28 Add R585 for OVERSH pull high by G.	
		20130729 Page28 Reserve R586-R589 for UART debug.	
		20130729 Page13 Reserve CN15, R590-R597 for XDP debug by Intel.	
		20130731 Page21 Add R590 replace JPT.	
		20130731 Page28 Del L18,L19 by SMT.	
		20130731 Page27 Del L14,L13,3 by SMT.	
		20130731 Page23 Change CN1 to DMQ1ZE/A0000 (SMD type: mic-als-f1342-22u4-2p) by SMT.	
		20130801 Page22 Change CN1 footprint to mic-a-m-quad1612p-nup	
		20130801 Page25 Reserve CPU_C207,C130	
		20130801 Page25 Add U13-U17,U12,U13,D33 for ESD	
		20130801 Page19: stuff R302 by G.	
		20130801 Page28 Un-Stuff R577 by G	
		20130802 Page5 Add C390-C396	
		20130802 Page5 Remove C396-C396	
		20130802 Change C31, C206, C244, C82, C248, C49, C262, C260, C41, C46, C42, C246, C21, C267, C23, C28, C25, C44, C27, C28, C24, C43, C45, C22, C247, C245,C14, C38, C50, C84, C151, C237, C240, C85, PC3, PC37 from CH1221M900 to CH1221M902.	
		20130805 Page28 Change EC_BRD_ID to 010 for PVT by G.	
		20130806 Page12 Change PR112 value to 2.50K by power.	
		20130806 Change C15, C206, C244, C82, C248, C49, C262, C260, C41, C46, C42, C246, C21, C267, C23, C28, C25, C44, C27, C28, C24, C43, C45, C22, C247, C245,C14, C38, C50, C84, C151, C237, C240, C85, PC3, PC37 from CH1221M902 to CH1221M903	
		20130806 Unstuff C12,C15,C26,C42,C49 for acoustic noise by Pwr.	
		20130813 Page25 Reserve Q27,Q28,R590,R600 for IAN leakage.	
		20130813 Change R55,R12,R54,R400,R152,R507,R152,R51,R53,R54 from 0 to shortpad.	
		20130817 Page21 Change R57&R1,R507,R501 from 0 to shortpad & del L1,L15 co lay by SMT.	
		20130821 Page18 Change R443,R445 from 0 to shortpad & del L13 co lay by SMT.	
		20130821 Page13 Change L16,L21 from CXP200000 to Behn by SMT.	
		20130822 Page25 Change CN13 footprint from R5502-2401-24P-R-SMT to R5502-2401-24P-L-SMT and swap CN13, Q28 pin define.	
		20130823 Page12 Del PC47 and Add PCN1	
		20130823 Page13 Del PC73 and Add PCN2	
		20130823 Page4 Change TP73, TP74, TP75 and TP76 footprint from TP2050 to TP2050	
		20130823 Page5 Change TP81 footprint from TP2050 to TP2050	
		20130823 Page21 Change TP91 footprint from TP2050 to TP2050	
		20130825 Change pin5 of U13, U34, U35, U36 and U37 power rail from PP5000 to PP5000_DSW	
		20130826 Page12 Change PC1 and PC37 from 22uF to 5uF. Unstuff others Vcc1n capacitors.	
20130826 Page21 Change C245, C244, C232, C24, C23, C21, C23, C26 and C48 from 22uF to 5uF. Unstuff others Vcc1n capacitors.			
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